



K20 Sub-Family Data Sheet

Supports the following:

MK20DX128ZVLQ10,
MK20DX128ZVMD10,
MK20DX256ZVLQ10,
MK20DX256ZVMD10,
MK20DN512ZVLQ10,
MK20DN512ZVMD10

Features

- Operating Characteristics
 - Voltage range: 1.71 to 3.6 V
 - Flash write voltage range: 1.71 to 3.6 V
 - Temperature range (ambient): -40 to 105°C
- Performance
 - Up to 100 MHz ARM Cortex-M4 core with DSP instructions delivering 1.25 Dhrystone MIPS per MHz
- Memories and memory interfaces
 - Up to 512 KB program flash memory on non-FlexMemory devices
 - Up to 128 KB RAM
 - Serial programming interface (EzPort)
 - FlexBus external bus interface
- Clocks
 - 3 to 32 MHz crystal oscillator
 - 32 kHz crystal oscillator
 - Multi-purpose clock generator
- System peripherals
 - 10 low-power modes to provide power optimization based on application requirements
 - Memory protection unit with multi-master protection
 - 16-channel DMA controller, supporting up to 64 request sources
 - External watchdog monitor
 - Software watchdog
 - Low-leakage wakeup unit
- Security and integrity modules
 - Hardware CRC module to support fast cyclic redundancy checks
 - 128-bit unique identification (ID) number per chip
- Human-machine interface
 - Low-power hardware touch sensor interface (TSI)
 - General-purpose input/output
- Analog modules
 - Two 16-bit SAR ADCs
 - Programmable gain amplifier (PGA) (up to x64) integrated into each ADC
 - Two 12-bit DACs
 - Three analog comparators (CMP) containing a 6-bit DAC and programmable reference input
 - Voltage reference
- Timers
 - Programmable delay block
 - Eight-channel motor control/general purpose/PWM timer
 - Two 2-channel quadrature decoder/general purpose timers
 - Periodic interrupt timers
 - 16-bit low-power timer
 - Carrier modulator transmitter
 - Real-time clock

K20P144M100SF2



Freescale reserves the right to change the detail specifications as may be required to permit improvements in the design of its products.

- Communication interfaces
 - USB full-/low-speed On-the-Go controller with on-chip transceiver
 - Two Controller Area Network (CAN) modules
 - Three SPI modules
 - Two I2C modules
 - Six UART modules
 - Secure Digital host controller (SDHC)
 - I2S module

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1 Ordering parts

1.1 Determining valid orderable parts

Valid orderable part numbers are provided on the web. To determine the orderable part numbers for this device, go to <http://www.freescale.com> and perform a part number search for the following device numbers: PK20 and MK20.

2 Part identification

2.1 Description

Part numbers for the chip have fields that identify the specific part. You can use the values of these fields to determine the specific part you have received.

2.2 Format

Part numbers for this device have the following format:

Q K## A M FFF R T PP CC N

2.3 Fields

This table lists the possible values for each field in the part number (not all combinations are valid):

| Field | Description | Values |
|-------|----------------------|--|
| Q | Qualification status | <ul style="list-style-type: none"> M = Fully qualified, general market flow P = Prequalification |
| K## | Kinetis family | <ul style="list-style-type: none"> K20 |
| A | Key attribute | <ul style="list-style-type: none"> D = Cortex-M4 w/ DSP F = Cortex-M4 w/ DSP and FPU |
| M | Flash memory type | <ul style="list-style-type: none"> N = Program flash only X = Program flash and FlexMemory |

Table continues on the next page...

Terminology and guidelines

| Field | Description | Values |
|-------|-----------------------------|--|
| FFF | Program flash memory size | <ul style="list-style-type: none">• 32 = 32 KB• 64 = 64 KB• 128 = 128 KB• 256 = 256 KB• 512 = 512 KB• 1M0 = 1 MB |
| R | Silicon revision | <ul style="list-style-type: none">• Z = Initial• (Blank) = Main• A = Revision after main |
| T | Temperature range (°C) | <ul style="list-style-type: none">• V = -40 to 105• C = -40 to 85 |
| PP | Package identifier | <ul style="list-style-type: none">• FM = 32 QFN (5 mm x 5 mm)• FT = 48 QFN (7 mm x 7 mm)• LF = 48 LQFP (7 mm x 7 mm)• EX = 64 LQFN (9 mm x 9 mm)• LH = 64 LQFP (10 mm x 10 mm)• LK = 80 LQFP (12 mm x 12 mm)• MB = 81 MAPBGA (8 mm x 8 mm)• LL = 100 LQFP (14 mm x 14 mm)• MC = 121 MAPBGA (8 mm x 8 mm)• LQ = 144 LQFP (20 mm x 20 mm)• MD = 144 MAPBGA (13 mm x 13 mm)• MF = 196 MAPBGA (15 mm x 15 mm)• MJ = 256 MAPBGA (17 mm x 17 mm) |
| CC | Maximum CPU frequency (MHz) | <ul style="list-style-type: none">• 5 = 50 MHz• 7 = 72 MHz• 10 = 100 MHz• 12 = 120 MHz• 15 = 150 MHz |
| N | Packaging type | <ul style="list-style-type: none">• R = Tape and reel• (Blank) = Trays |

2.4 Example

This is an example part number:

MK20DN512ZVMD10

3 Terminology and guidelines

3.1 Definition: Operating requirement

An *operating requirement* is a specified value or range of values for a technical characteristic that you must guarantee during operation to avoid incorrect operation and possibly decreasing the useful life of the chip.

3.1.1 Example

This is an example of an operating requirement, which you must meet for the accompanying operating behaviors to be guaranteed:

| Symbol | Description | Min. | Max. | Unit |
|-----------------|---------------------------|------|------|------|
| V _{DD} | 1.0 V core supply voltage | 0.9 | 1.1 | V |

3.2 Definition: Operating behavior

An *operating behavior* is a specified value or range of values for a technical characteristic that are guaranteed during operation if you meet the operating requirements and any other specified conditions.

3.2.1 Example

This is an example of an operating behavior, which is guaranteed if you meet the accompanying operating requirements:

| Symbol | Description | Min. | Max. | Unit |
|-----------------|--|------|------|------|
| I _{WP} | Digital I/O weak pullup/pulldown current | 10 | 130 | μA |

3.3 Definition: Attribute

An *attribute* is a specified value or range of values for a technical characteristic that are guaranteed, regardless of whether you meet the operating requirements.

3.3.1 Example

This is an example of an attribute:

| Symbol | Description | Min. | Max. | Unit |
|--------|------------------------------------|------|------|------|
| CIN_D | Input capacitance: digital pins | — | 7 | pF |

3.4 Definition: Rating

A *rating* is a minimum or maximum value of a technical characteristic that, if exceeded, may cause permanent chip failure:

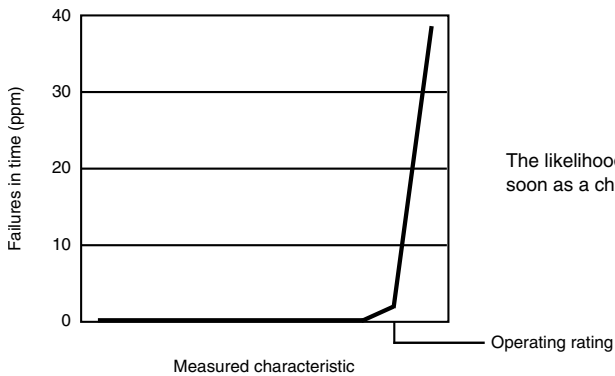
- *Operating ratings* apply during operation of the chip.
- *Handling ratings* apply when the chip is not powered.

3.4.1 Example

This is an example of an operating rating:

| Symbol | Description | Min. | Max. | Unit |
|-----------------|------------------------------|------|------|------|
| V _{DD} | 1.0 V core supply voltage | -0.3 | 1.2 | V |

3.5 Result of exceeding a rating



The likelihood of permanent chip failure increases rapidly as soon as a characteristic begins to exceed one of its operating ratings.

3.6 Relationship between ratings and operating requirements

| | | | | | | | |
|--|---|--|---|--|--|-------------------------------------|--|
| Operating or handling rating (min.) | | Operating requirement (min.) | | Operating requirement (max.) | | Operating or handling rating (max.) | |
| Fatal range - Probable permanent failure | Limited operating range - No permanent failure - Possible decreased life - Possible incorrect operation | Normal operating range - No permanent failure - Correct operation | Limited operating range - No permanent failure - Possible decreased life - Possible incorrect operation | Fatal range - Probable permanent failure | | | |
| Handling range - No permanent failure | | | | | | | |

3.7 Guidelines for ratings and operating requirements

Follow these guidelines for ratings and operating requirements:

- Never exceed any of the chip's ratings.
- During normal operation, don't exceed any of the chip's operating requirements.
- If you must exceed an operating requirement at times other than during normal operation (for example, during power sequencing), limit the duration as much as possible.

3.8 Definition: Typical value

A *typical value* is a specified value for a technical characteristic that:

- Lies within the range of values specified by the operating behavior
- Given the typical manufacturing process, is representative of that characteristic during operation when you meet the typical-value conditions or other specified conditions

Typical values are provided as design guidelines and are neither tested nor guaranteed.

3.8.1 Example 1

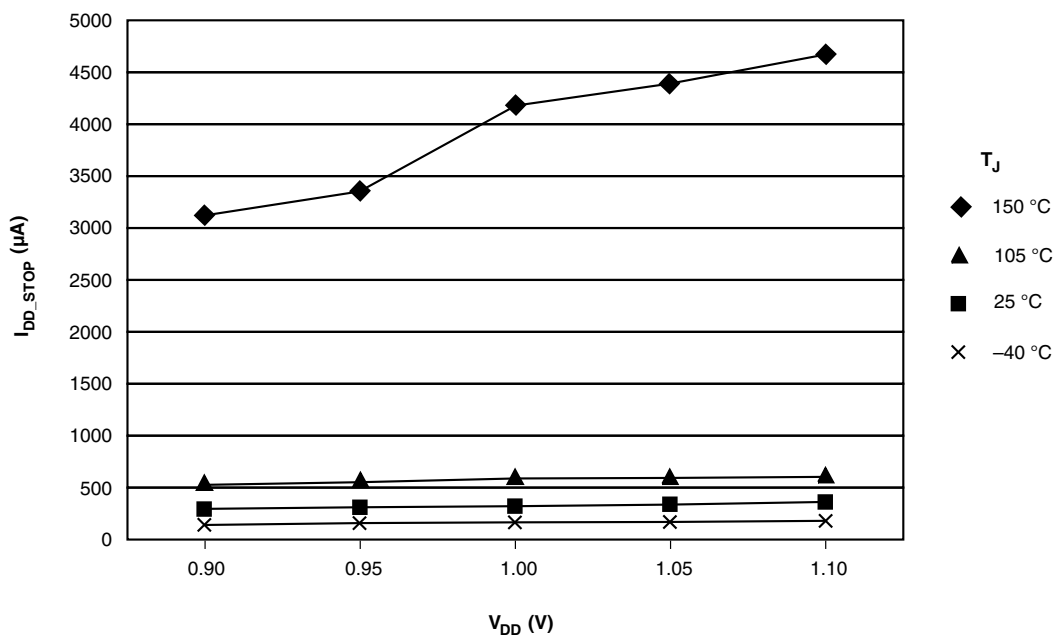
This is an example of an operating behavior that includes a typical value:

Ratings

| Symbol | Description | Min. | Typ. | Max. | Unit |
|----------|--|------|------|------|---------|
| I_{WP} | Digital I/O weak pullup/pulldown current | 10 | 70 | 130 | μA |

3.8.2 Example 2

This is an example of a chart that shows typical values for various voltage and temperature conditions:



3.9 Typical value conditions

Typical values assume you meet the following conditions (or other conditions as specified):

| Symbol | Description | Value | Unit |
|----------|----------------------|-------|-------------|
| T_A | Ambient temperature | 25 | $^{\circ}C$ |
| V_{DD} | 3.3 V supply voltage | 3.3 | V |

4 Ratings

4.1 Thermal handling ratings

| Symbol | Description | Min. | Max. | Unit | Notes |
|------------------|-------------------------------|------|------|------|-------|
| T _{STG} | Storage temperature | -55 | 150 | °C | 1 |
| T _{SDR} | Solder temperature, lead-free | — | 260 | °C | 2 |
| | Solder temperature, leaded | — | 245 | | |

1. Determined according to JEDEC Standard JESD22-A103, *High Temperature Storage Life*.
2. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

4.2 Moisture handling ratings

| Symbol | Description | Min. | Max. | Unit | Notes |
|--------|----------------------------|------|------|------|-------|
| MSL | Moisture sensitivity level | — | 3 | — | 1 |

1. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

4.3 ESD handling ratings

| Symbol | Description | Min. | Max. | Unit | Notes |
|------------------|---|-------|-------|------|-------|
| V _{HBM} | Electrostatic discharge voltage, human body model | -2000 | +2000 | V | 1 |
| V _{CDM} | Electrostatic discharge voltage, charged-device model | -500 | +500 | V | 2 |
| I _{LAT} | Latch-up current at ambient temperature of 105°C | -100 | +100 | mA | |

1. Determined according to JEDEC Standard JESD22-A114, *Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)*.
2. Determined according to JEDEC Standard JESD22-C101, *Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components*.

4.4 Voltage and current operating ratings

| Symbol | Description | Min. | Max. | Unit |
|------------------|---|------|------|------|
| V _{DD} | Digital supply voltage | -0.3 | 3.8 | V |
| I _{DD} | Digital supply current | — | 185 | mA |
| V _{DIO} | Digital input voltage (except RESET, EXTAL, and XTAL) | -0.3 | 5.5 | V |

Table continues on the next page...

General

| Symbol | Description | Min. | Max. | Unit |
|---------------|---|----------------|----------------|------|
| V_{AIO} | Analog ¹ , \overline{RESET} , EXTAL, and XTAL input voltage | -0.3 | $V_{DD} + 0.3$ | V |
| I_D | Instantaneous maximum current single pin limit (applies to all port pins) | -25 | 25 | mA |
| V_{DDA} | Analog supply voltage | $V_{DD} - 0.3$ | $V_{DD} + 0.3$ | V |
| V_{USB_DP} | USB_DP input voltage | -0.3 | 3.63 | V |
| V_{USB_DM} | USB_DM input voltage | -0.3 | 3.63 | V |
| VREGIN | USB regulator input | -0.3 | 6.0 | V |
| V_{BAT} | RTC battery supply voltage | -0.3 | 3.8 | V |

1. Analog pins are defined as pins that do not have an associated general purpose I/O port function.

5 General

5.1 AC electrical characteristics

Unless otherwise specified, propagation delays are measured from the 50% to the 50% point, and rise and fall times are measured at the 20% and 80% points, as shown in the following figure.

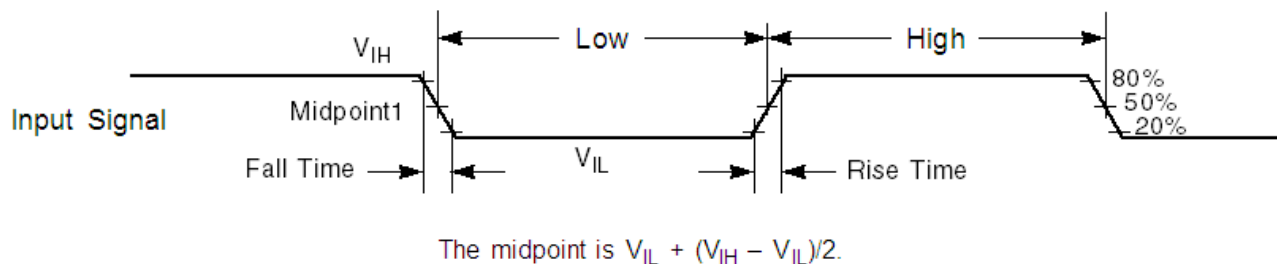


Figure 1. Input signal measurement reference

All digital I/O switching characteristics assume:

1. output pins
 - have $C_L=30\text{pF}$ loads,
 - are configured for fast slew rate ($\text{PORTx_PCRn[SRE]}=0$), and
 - are configured for high drive strength ($\text{PORTx_PCRn[DSE]}=1$)
2. input pins
 - have their passive filter disabled ($\text{PORTx_PCRn[PFE]}=0$)

5.2 Nonswitching electrical specifications

5.2.1 Voltage and current operating requirements

Table 1. Voltage and current operating requirements

| Symbol | Description | Min. | Max. | Unit | Notes |
|------------------------------------|--|---|---|--------|-------|
| V _{DD} | Supply voltage | 1.71 | 3.6 | V | |
| V _{DDA} | Analog supply voltage | 1.71 | 3.6 | V | |
| V _{DD} – V _{DDA} | V _{DD} -to-V _{DDA} differential voltage | -0.1 | 0.1 | V | |
| V _{SS} – V _{SSA} | V _{SS} -to-V _{SSA} differential voltage | -0.1 | 0.1 | V | |
| V _{BAT} | RTC battery supply voltage | 1.71 | 3.6 | V | |
| V _{IH} | Input high voltage <ul style="list-style-type: none"> • 2.7 V ≤ V_{DD} ≤ 3.6 V • 1.7 V ≤ V_{DD} ≤ 2.7 V | 0.7 × V _{DD} 0.75 × V _{DD} | — — | V V | |
| V _{IL} | Input low voltage <ul style="list-style-type: none"> • 2.7 V ≤ V_{DD} ≤ 3.6 V • 1.7 V ≤ V_{DD} ≤ 2.7 V | — — | 0.35 × V _{DD} 0.3 × V _{DD} | V V | |
| V _{HYS} | Input hysteresis | 0.06 × V _{DD} | — | V | |
| I _{ICDIO} | Digital pin negative DC injection current — single pin <ul style="list-style-type: none"> • V_{IN} < V_{SS}-0.3V | -5 | — | mA | 1 |
| I _{ICAIO} | Analog ² , EXTAL, and XTAL pin DC injection current — single pin <ul style="list-style-type: none"> • V_{IN} < V_{SS}-0.3V (Negative current injection) • V_{IN} > V_{DD}+0.3V (Positive current injection) | -5 — | — +5 | mA | 3 |
| I _{ICcont} | Contiguous pin DC injection current —regional limit, includes sum of negative injection currents or sum of positive injection currents of 16 contiguous pins <ul style="list-style-type: none"> • Negative current injection • Positive current injection | -25 — | — +25 | mA | |
| V _{RAM} | V _{DD} voltage required to retain RAM | 1.2 | — | V | |
| V _{RFVBAT} | V _{BAT} voltage required to retain the VBAT register file | V _{POR_VBAT} | — | V | |

- All 5 volt tolerant digital I/O pins are internally clamped to V_{SS} through a ESD protection diode. There is no diode connection to V_{DD}. If V_{IN} greater than V_{DIO_MIN} (=V_{SS}-0.3V) is observed, then there is no need to provide current limiting resistors at the pads. If this limit cannot be observed then a current limiting resistor is required. The negative DC injection current limiting resistor is calculated as $R=(V_{DIO_MIN}-V_{IN})/|I_{IC}|$.
- Analog pins are defined as pins that do not have an associated general purpose I/O port function.
- All analog pins are internally clamped to V_{SS} and V_{DD} through ESD protection diodes. If V_{IN} is greater than V_{AIO_MIN} (=V_{SS}-0.3V) and V_{IN} is less than V_{AIO_MAX}(=V_{DD}+0.3V) is observed, then there is no need to provide current limiting resistors at the pads. If these limits cannot be observed then a current limiting resistor is required. The negative DC injection current limiting resistor is calculated as $R=(V_{AIO_MIN}-V_{IN})/|I_{IC}|$. The positive injection current limiting resistor is calculated as $R=(V_{IN}-V_{AIO_MAX})/|I_{IC}|$. Select the larger of these two calculated resistances.

5.2.2 LVD and POR operating requirements

Table 2. V_{DD} supply LVD and POR operating requirements

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-------------|--|------|------|------|------|-------|
| V_{POR} | Falling VDD POR detect voltage | 0.8 | 1.1 | 1.5 | V | |
| V_{LVDH} | Falling low-voltage detect threshold — high range (LVDV=01) | 2.48 | 2.56 | 2.64 | V | |
| V_{LVW1H} | Low-voltage warning thresholds — high range <ul style="list-style-type: none"> • Level 1 falling (LVWV=00) • Level 2 falling (LVWV=01) • Level 3 falling (LVWV=10) • Level 4 falling (LVWV=11) | 2.62 | 2.70 | 2.78 | V | 1 |
| V_{LVW2H} | | 2.72 | 2.80 | 2.88 | V | |
| V_{LVW3H} | | 2.82 | 2.90 | 2.98 | V | |
| V_{LVW4H} | | 2.92 | 3.00 | 3.08 | V | |
| V_{HYSH} | Low-voltage inhibit reset/recover hysteresis — high range | — | ±80 | — | mV | |
| V_{LVDL} | Falling low-voltage detect threshold — low range (LVDV=00) | 1.54 | 1.60 | 1.66 | V | |
| V_{LVW1L} | Low-voltage warning thresholds — low range <ul style="list-style-type: none"> • Level 1 falling (LVWV=00) • Level 2 falling (LVWV=01) • Level 3 falling (LVWV=10) • Level 4 falling (LVWV=11) | 1.74 | 1.80 | 1.86 | V | 1 |
| V_{LVW2L} | | 1.84 | 1.90 | 1.96 | V | |
| V_{LVW3L} | | 1.94 | 2.00 | 2.06 | V | |
| V_{LVW4L} | | 2.04 | 2.10 | 2.16 | V | |
| V_{HYSL} | Low-voltage inhibit reset/recover hysteresis — low range | — | ±60 | — | mV | |
| V_{BG} | Bandgap voltage reference | 0.97 | 1.00 | 1.03 | V | |
| t_{LPO} | Internal low power oscillator period — factory trimmed | 900 | 1000 | 1100 | μs | |

1. Rising thresholds are falling threshold + hysteresis voltage

Table 3. VBAT power operating requirements

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------------|--|------|------|------|------|-------|
| V_{POR_VBAT} | Falling VBAT supply POR detect voltage | 0.8 | 1.1 | 1.5 | V | |

5.2.3 Voltage and current operating behaviors

Table 4. Voltage and current operating behaviors

| Symbol | Description | Min. | Max. | Unit | Notes |
|-----------|--|----------------|-------|---------------|-------|
| V_{OH} | Output high voltage — high drive strength <ul style="list-style-type: none"> $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OH} = -9\text{mA}$ $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OH} = -3\text{mA}$ | $V_{DD} - 0.5$ | — | V | |
| | Output high voltage — low drive strength <ul style="list-style-type: none"> $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OH} = -2\text{mA}$ $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OH} = -0.6\text{mA}$ | $V_{DD} - 0.5$ | — | V | |
| I_{OHT} | Output high current total for all ports | — | 100 | mA | |
| V_{OL} | Output low voltage — high drive strength <ul style="list-style-type: none"> $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OL} = 9\text{mA}$ $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OL} = 3\text{mA}$ | — | 0.5 | V | |
| | Output low voltage — low drive strength <ul style="list-style-type: none"> $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OL} = 2\text{mA}$ $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OL} = 0.6\text{mA}$ | — | 0.5 | V | |
| I_{OLT} | Output low current total for all ports | — | 100 | mA | |
| I_{IN} | Input leakage current (per pin) for full temperature range | — | 1 | μA | 1 |
| I_{IN} | Input leakage current (per pin) at 25°C | — | 0.025 | μA | 1 |
| I_{OZ} | Hi-Z (off-state) leakage current (per pin) | — | 1 | μA | |
| R_{PU} | Internal pullup resistors | 20 | 50 | k Ω | 2 |
| R_{PD} | Internal pulldown resistors | 20 | 50 | k Ω | 3 |

1. Measured at $V_{DD}=3.6\text{V}$
2. Measured at V_{DD} supply voltage = V_{DD} min and $V_{input} = V_{SS}$
3. Measured at V_{DD} supply voltage = V_{DD} min and $V_{input} = V_{DD}$

5.2.4 Power mode transition operating behaviors

All specifications except t_{POR} , and $V_{LLSx} \rightarrow \text{RUN}$ recovery times in the following table assume this clock configuration:

- CPU and system clocks = 100 MHz
- Bus clock = 50 MHz
- FlexBus clock = 50 MHz
- Flash clock = 25 MHz

Table 5. Power mode transition operating behaviors

| Symbol | Description | Min. | Max. | Unit | Notes |
|-----------|--|------|------|---------|-------|
| t_{POR} | After a POR event, amount of time from the point V_{DD} reaches 1.71 V to execution of the first instruction across the operating temperature range of the chip. | — | 300 | μs | 1 |
| | • VLLS1 → RUN | — | 112 | μs | |
| | • VLLS2 → RUN | — | 74 | μs | |
| | • VLLS3 → RUN | — | 73 | μs | |
| | • LLS → RUN | — | 5.9 | μs | |
| | • VLPS → RUN | — | 5.8 | μs | |
| | • STOP → RUN | — | 4.2 | μs | |

1. Normal boot (FTFL_OPT[LPBOOT]=1)

5.2.5 Power consumption operating behaviors

Table 6. Power consumption operating behaviors

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|----------------|---|------|------|----------|------|-------|
| I_{DDA} | Analog supply current | — | — | See note | mA | 1 |
| I_{DD_RUN} | Run mode current — all peripheral clocks disabled, code executing from flash | | | | | 2 |
| | • @ 1.8V | — | 45 | 70 | mA | |
| | • @ 3.0V | — | 47 | 72 | mA | |
| I_{DD_RUN} | Run mode current — all peripheral clocks enabled, code executing from flash | | | | | 3, 4 |
| | • @ 1.8V | — | 61 | 85 | mA | |
| | • @ 3.0V | | | | | |
| | • @ 25°C | — | 63 | 71 | mA | |
| | • @ 125°C | — | 72 | 87 | mA | |
| I_{DD_WAIT} | Wait mode high frequency current at 3.0 V — all peripheral clocks disabled | — | 35 | — | mA | 2 |
| I_{DD_WAIT} | Wait mode reduced frequency current at 3.0 V — all peripheral clocks disabled | — | 15 | — | mA | 5 |
| I_{DD_VLPR} | Very-low-power run mode current at 3.0 V — all peripheral clocks disabled | — | N/A | — | mA | 6 |

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------------------|---|------|------|------|------|-------|
| I _{DD_VLPR} | Very-low-power run mode current at 3.0 V — all peripheral clocks enabled | — | N/A | — | mA | 7 |
| I _{DD_VLPW} | Very-low-power wait mode current at 3.0 V — all peripheral clocks disabled | — | N/A | — | mA | 8 |
| I _{DD_STOP} | Stop mode current at 3.0 V <ul style="list-style-type: none"> @ -40 to 25°C @ 70°C @ 105°C | — | 0.59 | 1.4 | mA | |
| | | — | 2.26 | 7.9 | mA | |
| | | — | 5.94 | 19.2 | mA | |
| I _{DD_VLPS} | Very-low-power stop mode current at 3.0 V <ul style="list-style-type: none"> @ -40 to 25°C @ 70°C @ 105°C | — | 93 | 435 | μA | |
| | | — | 520 | 2000 | μA | |
| | | — | 1350 | 4000 | μA | |
| I _{DD_LLS} | Low leakage stop mode current at 3.0 V <ul style="list-style-type: none"> @ -40 to 25°C @ 70°C @ 105°C | — | 4.8 | 20 | μA | 9 |
| | | — | 28 | 68 | μA | |
| | | — | 126 | 270 | μA | |
| I _{DD_VLLS3} | Very low-leakage stop mode 3 current at 3.0 V <ul style="list-style-type: none"> @ -40 to 25°C @ 70°C @ 105°C | — | 3.1 | 8.9 | μA | 9 |
| | | — | 17 | 35 | μA | |
| | | — | 82 | 148 | μA | |
| I _{DD_VLLS2} | Very low-leakage stop mode 2 current at 3.0 V <ul style="list-style-type: none"> @ -40 to 25°C @ 70°C @ 105°C | — | 2.2 | 5.4 | μA | |
| | | — | 7.1 | 12.5 | μA | |
| | | — | 41 | 125 | μA | |
| I _{DD_VLLS1} | Very low-leakage stop mode 1 current at 3.0 V <ul style="list-style-type: none"> @ -40 to 25°C @ 70°C @ 105°C | — | 2.1 | 7.6 | μA | |
| | | — | 6.2 | 13.5 | μA | |
| | | — | 30 | 46 | μA | |
| I _{DD_VBAT} | Average current with RTC and 32kHz disabled at 3.0 V <ul style="list-style-type: none"> @ -40 to 25°C @ 70°C @ 105°C | — | 0.33 | 0.39 | μA | |
| | | — | 0.60 | 0.78 | μA | |
| | | — | 1.97 | 2.9 | μA | |

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|----------------------|---|------|------|------|------|-------|
| I _{DD_VBAT} | Average current when CPU is not accessing RTC registers | | | | | 10 |
| | • @ 1.8V | | | | | |
| | • @ -40 to 25°C | — | 0.71 | 0.81 | μA | |
| | • @ 70°C | — | 1.01 | 1.3 | μA | |
| | • @ 105°C | — | 2.82 | 4.3 | μA | |
| | • @ 3.0V | | | | | |
| | • @ -40 to 25°C | — | 0.84 | 0.94 | μA | |
| | • @ 70°C | — | 1.17 | 1.5 | μA | |
| | • @ 105°C | — | 3.16 | 4.6 | μA | |

1. The analog supply current is the sum of the active or disabled current for each of the analog modules on the device. See each module's specification for its supply current.
2. 100MHz core and system clock, 50MHz bus and FlexBus clock, and 25MHz flash clock . MCG configured for FEI mode. All peripheral clocks disabled.
3. 100MHz core and system clock, 50MHz bus and FlexBus clock, and 25MHz flash clock. MCG configured for FEI mode. All peripheral clocks enabled.
4. Max values are measured with CPU executing DSP instructions.
5. 25MHz core and system clock, 25MHz bus clock, and 12.5MHz FlexBus and flash clock. MCG configured for FEI mode.
6. 2 MHz core, system, FlexBus, and bus clock and 1MHz flash clock. MCG configured for BLPE mode. All peripheral clocks disabled. Code executing from flash.
7. 2 MHz core, system, FlexBus, and bus clock and 1MHz flash clock. MCG configured for BLPE mode. All peripheral clocks enabled but peripherals are not in active operation. Code executing from flash.
8. 2 MHz core, system, FlexBus, and bus clock and 1MHz flash clock. MCG configured for BLPE mode. All peripheral clocks disabled.
9. Data reflects devices with 128 KB of RAM. For devices with 64 KB of RAM, power consumption is reduced by 2 μA. For devices with 32 KB of RAM, power consumption is reduced by 3 μA.
10. Includes 32kHz oscillator current and RTC operation.

5.2.5.1 Diagram: Typical IDD_RUN operating behavior

The following data was measured under these conditions:

- MCG in FBE mode for 50 MHz and lower frequencies. MCG in FEE mode at greater than 50 MHz frequencies
- USB regulator disabled
- No GPIOs toggled
- Code execution from flash with cache enabled
- For the ALLOFF curve, all peripheral clocks are disabled except FTFL

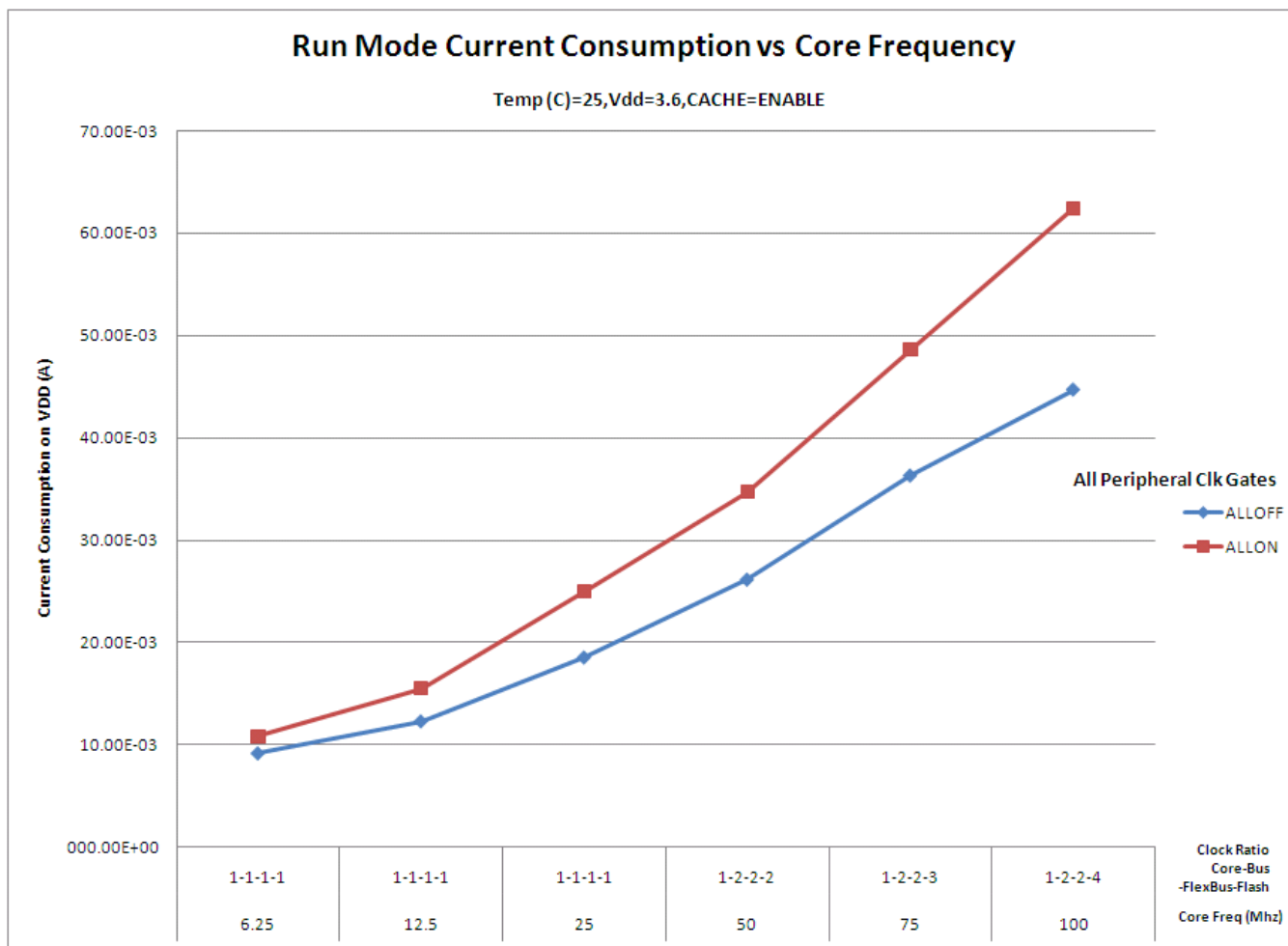


Figure 2. Run mode supply current vs. core frequency

5.2.6 EMC radiated emissions operating behaviors

Table 7. EMC radiated emissions operating behaviors for 144LQFP

| Symbol | Description | Frequency band (MHz) | Typ. | Unit | Notes |
|---------------------|------------------------------------|----------------------|------|------|-------|
| V _{RE1} | Radiated emissions voltage, band 1 | 0.15–50 | 23 | dBμV | 1, 2 |
| V _{RE2} | Radiated emissions voltage, band 2 | 50–150 | 27 | dBμV | |
| V _{RE3} | Radiated emissions voltage, band 3 | 150–500 | 28 | dBμV | |
| V _{RE4} | Radiated emissions voltage, band 4 | 500–1000 | 14 | dBμV | |
| V _{RE_IEC} | IEC level | 0.15–1000 | K | — | 2, 3 |

1. Determined according to IEC Standard 61967-1, *Integrated Circuits - Measurement of Electromagnetic Emissions, 150 kHz to 1 GHz Part 1: General Conditions and Definitions* and IEC Standard 61967-2, *Integrated Circuits - Measurement of Electromagnetic Emissions, 150 kHz to 1 GHz Part 2: Measurement of Radiated Emissions—TEM Cell and Wideband TEM Cell Method*. Measurements were made while the microcontroller was running basic application code. The reported emission level is the value of the maximum measured emission, rounded up to the next whole number, from among the measured orientations in each frequency range.

General

- $V_{DD} = 3.3\text{ V}$, $T_A = 25\text{ }^\circ\text{C}$, $f_{OSC} = 12\text{ MHz}$ (crystal), $f_{SYS} = 96\text{ MHz}$, $f_{BUS} = 48\text{ MHz}$
- Specified according to Annex D of IEC Standard 61967-2, *Measurement of Radiated Emissions—TEM Cell and Wideband TEM Cell Method*

5.2.7 Designing with radiated emissions in mind

To find application notes that provide guidance on designing your system to minimize interference from radiated emissions:

- Go to <http://www.freescale.com>.
- Perform a keyword search for “EMC design.”

5.2.8 Capacitance attributes

Table 8. Capacitance attributes

| Symbol | Description | Min. | Max. | Unit |
|-------------|---------------------------------|------|------|------|
| C_{IN_A} | Input capacitance: analog pins | — | 7 | pF |
| C_{IN_D} | Input capacitance: digital pins | — | 7 | pF |

5.3 Switching specifications

5.3.1 Device clock specifications

Table 9. Device clock specifications

| Symbol | Description | Min. | Max. | Unit | Notes |
|-----------------|--|------|------|------|-------|
| Normal run mode | | | | | |
| f_{SYS} | System and core clock | — | 100 | MHz | |
| f_{SYS_USB} | System and core clock when Full Speed USB in operation | 20 | — | MHz | |
| f_{BUS} | Bus clock | — | 50 | MHz | |
| FB_CLK | FlexBus clock | — | 50 | MHz | |
| f_{FLASH} | Flash clock | — | 25 | MHz | |
| f_{LPTMR} | LPTMR clock | — | 25 | MHz | |

5.3.2 General switching specifications

These general purpose specifications apply to all signals configured for GPIO, UART, CAN, CMT, and I²C signals.

Table 10. General switching specifications

| Symbol | Description | Min. | Max. | Unit | Notes |
|--------|---|------|------|------------------|-------|
| | GPIO pin interrupt pulse width (digital glitch filter disabled) — Synchronous path | 1.5 | — | Bus clock cycles | 1 |
| | GPIO pin interrupt pulse width (digital glitch filter disabled, analog filter enabled) — Asynchronous path | 100 | — | ns | 2 |
| | GPIO pin interrupt pulse width (digital glitch filter disabled, analog filter disabled) — Asynchronous path | 16 | — | ns | 2 |
| | External reset pulse width (digital glitch filter disabled) | 100 | — | ns | 2 |
| | Mode select (EZP_CS) hold time after reset deassertion | 2 | — | Bus clock cycles | |
| | Port rise and fall time (high drive strength) <ul style="list-style-type: none"> • Slew disabled <ul style="list-style-type: none"> • $1.71 \leq V_{DD} \leq 2.7V$ • $2.7 \leq V_{DD} \leq 3.6V$ • Slew enabled <ul style="list-style-type: none"> • $1.71 \leq V_{DD} \leq 2.7V$ • $2.7 \leq V_{DD} \leq 3.6V$ | — | 12 | ns | 3 |
| | | — | 6 | ns | |
| | | — | 36 | ns | |
| | | — | 24 | ns | |
| | Port rise and fall time (low drive strength) <ul style="list-style-type: none"> • Slew disabled <ul style="list-style-type: none"> • $1.71 \leq V_{DD} \leq 2.7V$ • $2.7 \leq V_{DD} \leq 3.6V$ • Slew enabled <ul style="list-style-type: none"> • $1.71 \leq V_{DD} \leq 2.7V$ • $2.7 \leq V_{DD} \leq 3.6V$ | — | 12 | ns | 4 |
| | | — | 6 | ns | |
| | | — | 36 | ns | |
| | | — | 24 | ns | |

1. The greater synchronous and asynchronous timing must be met.
2. This is the shortest pulse that is guaranteed to be recognized.
3. 75pF load
4. 15pF load

5.4 Thermal specifications

5.4.1 Thermal operating requirements

Table 11. Thermal operating requirements

| Symbol | Description | Min. | Max. | Unit |
|--------|--------------------------|------|------|------|
| T_J | Die junction temperature | -40 | 125 | °C |
| T_A | Ambient temperature | -40 | 105 | °C |

5.4.2 Thermal attributes

| Board type | Symbol | Description | 144 LQFP | 144 MAPBGA | Unit | Notes |
|-------------------|------------------|---|----------|------------|------|-------|
| Single-layer (1s) | $R_{\theta JA}$ | Thermal resistance, junction to ambient (natural convection) | 45 | 48 | °C/W | 1 |
| Four-layer (2s2p) | $R_{\theta JA}$ | Thermal resistance, junction to ambient (natural convection) | 36 | 29 | °C/W | 1 |
| Single-layer (1s) | $R_{\theta JMA}$ | Thermal resistance, junction to ambient (200 ft./min. air speed) | 36 | 38 | °C/W | 1 |
| Four-layer (2s2p) | $R_{\theta JMA}$ | Thermal resistance, junction to ambient (200 ft./min. air speed) | 30 | 25 | °C/W | 1 |
| — | $R_{\theta JB}$ | Thermal resistance, junction to board | 24 | 16 | °C/W | 2 |
| — | $R_{\theta JC}$ | Thermal resistance, junction to case | 9 | 9 | °C/W | 3 |
| — | Ψ_{JT} | Thermal characterization parameter, junction to package top outside center (natural convection) | 2 | 2 | °C/W | 4 |

1. Determined according to JEDEC Standard JESD51-2, *Integrated Circuits Thermal Test Method Environmental Conditions—Natural Convection (Still Air)*, or EIA/JEDEC Standard JESD51-6, *Integrated Circuit Thermal Test Method Environmental Conditions—Forced Convection (Moving Air)*.

2. Determined according to JEDEC Standard JESD51-8, *Integrated Circuit Thermal Test Method Environmental Conditions—Junction-to-Board*.
3. Determined according to Method 1012.1 of MIL-STD 883, *Test Method Standard, Microcircuits*, with the cold plate temperature used for the case temperature. The value includes the thermal resistance of the interface material between the top of the package and the cold plate.
4. Determined according to JEDEC Standard JESD51-2, *Integrated Circuits Thermal Test Method Environmental Conditions—Natural Convection (Still Air)*.

6 Peripheral operating requirements and behaviors

6.1 Core modules

6.1.1 Debug trace timing specifications

Table 12. Debug trace operating behaviors

| Symbol | Description | Min. | Max. | Unit |
|-----------|--------------------------|---------------------|------|------|
| T_{cyc} | Clock period | Frequency dependent | | MHz |
| T_{wl} | Low pulse width | 2 | — | ns |
| T_{wh} | High pulse width | 2 | — | ns |
| T_r | Clock and data rise time | — | 3 | ns |
| T_f | Clock and data fall time | — | 3 | ns |
| T_s | Data setup | 3 | — | ns |
| T_h | Data hold | 2 | — | ns |

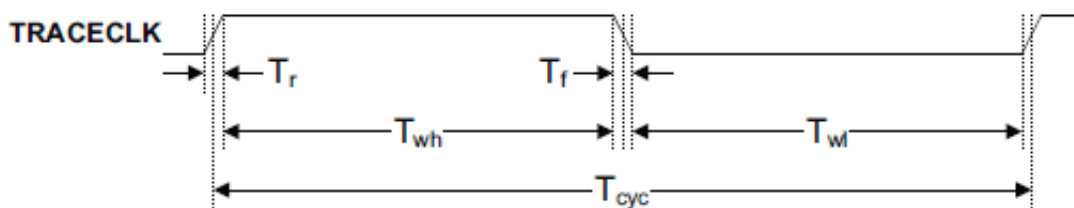


Figure 3. TRACE_CLKOUT specifications

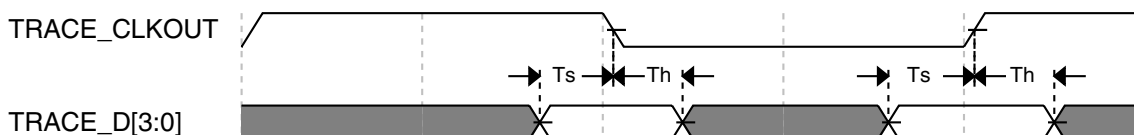


Figure 4. Trace data specifications

6.1.2 JTAG electricals

Table 13. JTAG limited voltage range electricals

| Symbol | Description | Min. | Max. | Unit |
|--------|--|----------------|----------------|----------------|
| | Operating voltage | 2.7 | 3.6 | V |
| J1 | TCLK frequency of operation <ul style="list-style-type: none"> Boundary Scan JTAG and CJTAG Serial Wire Debug | 0 0 0 | 10 25 50 | MHz |
| J2 | TCLK cycle period | 1/J1 | — | ns |
| J3 | TCLK clock pulse width <ul style="list-style-type: none"> Boundary Scan JTAG and CJTAG Serial Wire Debug | 50 20 10 | — — — | ns ns ns |
| J4 | TCLK rise and fall times | — | 3 | ns |
| J5 | Boundary scan input data setup time to TCLK rise | 20 | — | ns |
| J6 | Boundary scan input data hold time after TCLK rise | 0 | — | ns |
| J7 | TCLK low to boundary scan output data valid | — | 25 | ns |
| J8 | TCLK low to boundary scan output high-Z | — | 25 | ns |
| J9 | TMS, TDI input data setup time to TCLK rise | 8 | — | ns |
| J10 | TMS, TDI input data hold time after TCLK rise | 1 | — | ns |
| J11 | TCLK low to TDO data valid | — | 17 | ns |
| J12 | TCLK low to TDO high-Z | — | 17 | ns |
| J13 | TRST assert time | 100 | — | ns |
| J14 | TRST setup time (negation) to TCLK high | 8 | — | ns |

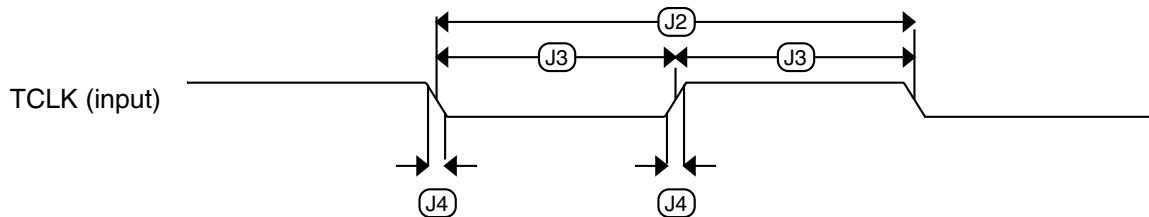
Table 14. JTAG full voltage range electricals

| Symbol | Description | Min. | Max. | Unit |
|--------|--|-------------|----------------|------|
| | Operating voltage | 1.71 | 3.6 | V |
| J1 | TCLK frequency of operation <ul style="list-style-type: none"> Boundary Scan JTAG and CJTAG Serial Wire Debug | 0 0 0 | 10 20 40 | MHz |
| J2 | TCLK cycle period | 1/J1 | — | ns |

Table continues on the next page...

Table 14. JTAG full voltage range electricals (continued)

| Symbol | Description | Min. | Max. | Unit |
|--------|--|------|------|------|
| J3 | TCLK clock pulse width | | | |
| | • Boundary Scan | 50 | — | ns |
| | • JTAG and CJTAG | 25 | — | ns |
| | • Serial Wire Debug | 12.5 | — | ns |
| J4 | TCLK rise and fall times | — | 3 | ns |
| J5 | Boundary scan input data setup time to TCLK rise | 20 | — | ns |
| J6 | Boundary scan input data hold time after TCLK rise | 0 | — | ns |
| J7 | TCLK low to boundary scan output data valid | — | 25 | ns |
| J8 | TCLK low to boundary scan output high-Z | — | 25 | ns |
| J9 | TMS, TDI input data setup time to TCLK rise | 8 | — | ns |
| J10 | TMS, TDI input data hold time after TCLK rise | 1.4 | — | ns |
| J11 | TCLK low to TDO data valid | — | 22.1 | ns |
| J12 | TCLK low to TDO high-Z | — | 22.1 | ns |
| J13 | TRST assert time | 100 | — | ns |
| J14 | TRST setup time (negation) to TCLK high | 8 | — | ns |

**Figure 5. Test clock input timing**

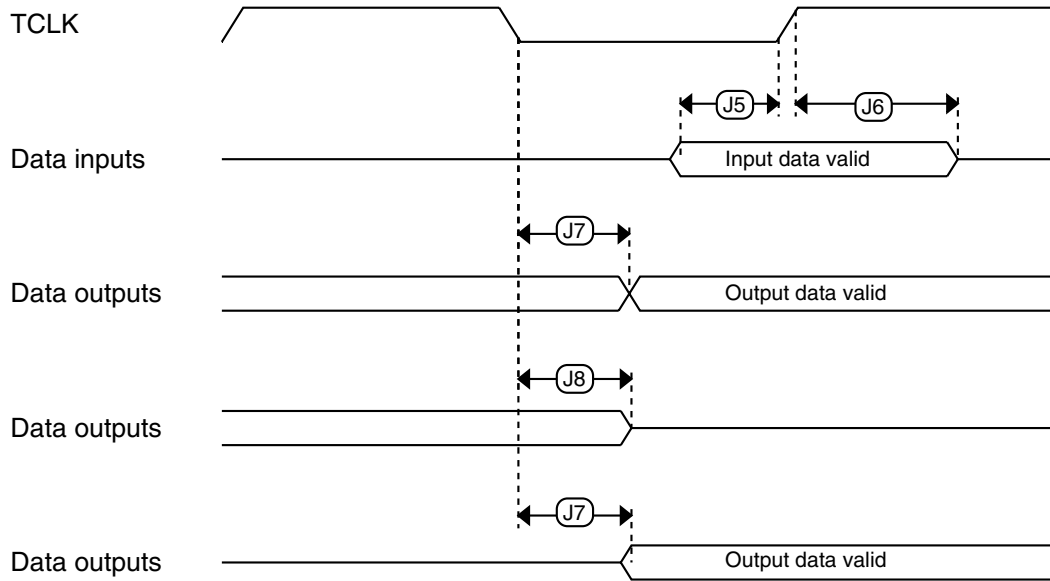


Figure 6. Boundary scan (JTAG) timing

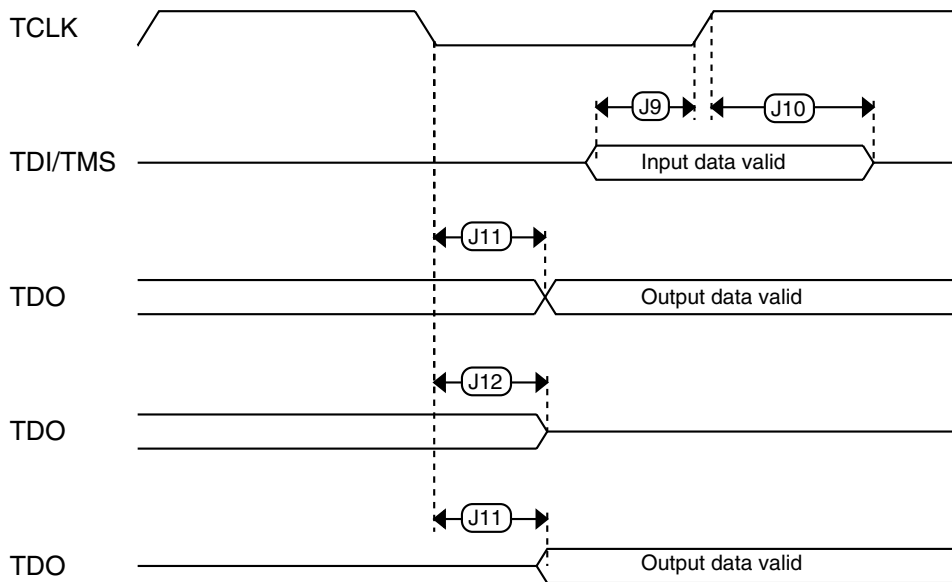
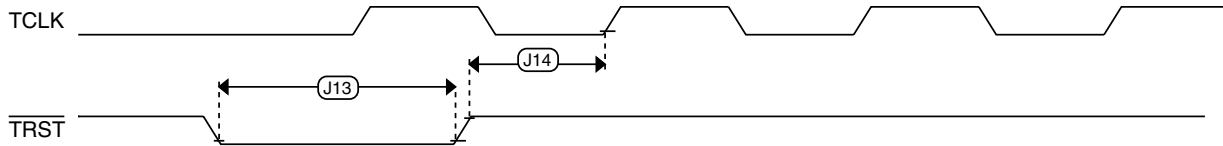


Figure 7. Test Access Port timing

Figure 8. $\overline{\text{TRST}}$ timing

6.2 System modules

There are no specifications necessary for the device's system modules.

6.3 Clock modules

6.3.1 MCG specifications

Table 15. MCG specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---------------------------------|--|------------------------------------|-----------|-----------|--------------------|-------|
| $f_{\text{ints_ft}}$ | Internal reference frequency (slow clock) — factory trimmed at nominal VDD and 25 °C | — | 32.768 | — | kHz | |
| $f_{\text{ints_t}}$ | Internal reference frequency (slow clock) — user trimmed | 31.25 | — | 38.2 | kHz | |
| I_{ints} | Internal reference (slow clock) current | — | 20 | — | μA | |
| $\Delta f_{\text{dco_res_t}}$ | Resolution of trimmed average DCO output frequency at fixed voltage and temperature — using SCTRIM and SCFTRIM | — | ± 0.3 | ± 0.6 | $\%f_{\text{dco}}$ | 1 |
| $\Delta f_{\text{dco_t}}$ | Total deviation of trimmed average DCO output frequency over fixed voltage and temperature range of 0–70°C | — | ± 1.5 | ± 4.5 | $\%f_{\text{dco}}$ | 1 |
| $f_{\text{intf_ft}}$ | Internal reference frequency (fast clock) — factory trimmed at nominal VDD and 25°C | — | 4 | — | MHz | |
| $f_{\text{intf_t}}$ | Internal reference frequency (fast clock) — user trimmed at nominal VDD and 25 °C | 3 | — | 5 | MHz | |
| I_{intf} | Internal reference (fast clock) current | — | 25 | — | μA | |
| $f_{\text{loc_low}}$ | Loss of external clock minimum frequency — RANGE = 00 | $(3/5) \times f_{\text{ints_t}}$ | — | — | kHz | |
| $f_{\text{loc_high}}$ | Loss of external clock minimum frequency — RANGE = 01, 10, or 11 | $(16/5) \times f_{\text{ints_t}}$ | — | — | kHz | |

Table continues on the next page...

Table 15. MCG specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes | |
|----------------------------|---|--|------|---------|---------------|-------|------|
| FLL | | | | | | | |
| $f_{\text{fll_ref}}$ | FLL reference frequency range | 31.25 | — | 39.0625 | kHz | | |
| f_{dco} | DCO output frequency range | Low range (DRS=00) $640 \times f_{\text{fll_ref}}$ | 20 | 20.97 | 25 | MHz | 2, 3 |
| | | Mid range (DRS=01) $1280 \times f_{\text{fll_ref}}$ | 40 | 41.94 | 50 | MHz | |
| | | Mid-high range (DRS=10) $1920 \times f_{\text{fll_ref}}$ | 60 | 62.91 | 75 | MHz | |
| | | High range (DRS=11) $2560 \times f_{\text{fll_ref}}$ | 80 | 83.89 | 100 | MHz | |
| $f_{\text{dco_t_DMX3}2}$ | DCO output frequency | Low range (DRS=00) $732 \times f_{\text{fll_ref}}$ | — | 23.99 | — | MHz | 4, 5 |
| | | Mid range (DRS=01) $1464 \times f_{\text{fll_ref}}$ | — | 47.97 | — | MHz | |
| | | Mid-high range (DRS=10) $2197 \times f_{\text{fll_ref}}$ | — | 71.99 | — | MHz | |
| | | High range (DRS=11) $2929 \times f_{\text{fll_ref}}$ | — | 95.98 | — | MHz | |
| $J_{\text{cyc_fll}}$ | FLL period jitter <ul style="list-style-type: none"> $f_{\text{VCO}} = 48 \text{ MHz}$ $f_{\text{VCO}} = 98 \text{ MHz}$ | — | 180 | — | ps | | |
| $t_{\text{fll_acquire}}$ | FLL target frequency acquisition time | — | — | 1 | ms | 6 | |
| PLL | | | | | | | |
| f_{vco} | VCO operating frequency | 48.0 | — | 100 | MHz | | |
| I_{pll} | PLL operating current <ul style="list-style-type: none"> PLL @ 96 MHz ($f_{\text{osc_hi_1}} = 8 \text{ MHz}$, $f_{\text{pll_ref}} = 2 \text{ MHz}$, VDIV multiplier = 48) | — | 1060 | — | μA | 7 | |
| | | — | 600 | — | μA | | |
| $f_{\text{pll_ref}}$ | PLL reference frequency range | 2.0 | — | 4.0 | MHz | | |
| $J_{\text{cyc_pll}}$ | PLL period jitter (RMS) <ul style="list-style-type: none"> $f_{\text{vco}} = 48 \text{ MHz}$ $f_{\text{vco}} = 100 \text{ MHz}$ | — | 120 | — | ps | 8 | |
| | | — | 50 | — | ps | | |

Table continues on the next page...

Table 15. MCG specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|------------------------|---|------------|------|--|------|-------|
| $J_{\text{acc_pll}}$ | PLL accumulated jitter over 1 μs (RMS) <ul style="list-style-type: none"> $f_{\text{vco}} = 48 \text{ MHz}$ $f_{\text{vco}} = 100 \text{ MHz}$ | — | 1350 | — | ps | 8 |
| | | — | 600 | — | ps | |
| D_{lock} | Lock entry frequency tolerance | ± 1.49 | — | ± 2.98 | % | |
| D_{unl} | Lock exit frequency tolerance | ± 4.47 | — | ± 5.97 | % | |
| $t_{\text{pll_lock}}$ | Lock detector detection time | — | — | $150 \times 10^{-6} + 1075(1/f_{\text{pll_ref}})$ | s | 9 |

1. This parameter is measured with the internal reference (slow clock) being used as a reference to the FLL (FEI clock mode).
2. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=0.
3. The resulting system clock frequencies should not exceed their maximum specified values. The DCO frequency deviation (Δf_{dco_t}) over voltage and temperature should be considered.
4. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=1.
5. The resulting clock frequency must not exceed the maximum specified clock frequency of the device.
6. This specification applies to any time the FLL reference source or reference divider is changed, trim value is changed, DMX32 bit is changed, DRS bits are changed, or changing from FLL disabled (BLPE, BLPI) to FLL enabled (FEI, FEE, FBE, FBI). If a crystal/resonator is being used as the reference, this specification assumes it is already running.
7. Excludes any oscillator currents that are also consuming power while PLL is in operation.
8. This specification was obtained using a Freescale developed PCB. PLL jitter is dependent on the noise characteristics of each PCB and results will vary.
9. This specification applies to any time the PLL VCO divider or reference divider is changed, or changing from PLL disabled (BLPE, BLPI) to PLL enabled (PBE, PEE). If a crystal/resonator is being used as the reference, this specification assumes it is already running.

6.3.2 Oscillator electrical specifications

This section provides the electrical characteristics of the module.

6.3.2.1 Oscillator DC electrical specifications

Table 16. Oscillator DC electrical specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|--------------------|---|------|------|------|---------------|-------|
| V_{DD} | Supply voltage | 1.71 | — | 3.6 | V | |
| I_{DDOSC} | Supply current — low-power mode (HGO=0) | | | | | 1 |
| | • 32 kHz | — | 500 | — | nA | |
| | • 4 MHz | — | 200 | — | μA | |
| | • 8 MHz (RANGE=01) | — | 300 | — | μA | |
| | • 16 MHz | — | 950 | — | μA | |
| | • 24 MHz | — | 1.2 | — | mA | |
| • 32 MHz | — | 1.5 | — | mA | | |

Table continues on the next page...

Table 16. Oscillator DC electrical specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|------------------------------|--|------|-----------------|------|------|-------|
| I _{DDOSC} | Supply current — high gain mode (HGO=1) | | | | | 1 |
| | • 32 kHz | — | 25 | — | μA | |
| | • 4 MHz | — | 400 | — | μA | |
| | • 8 MHz (RANGE=01) | — | 500 | — | μA | |
| | • 16 MHz | — | 2.5 | — | mA | |
| | • 24 MHz | — | 3 | — | mA | |
| • 32 MHz | — | 4 | — | mA | | |
| C _x | EXTAL load capacitance | — | — | — | | 2, 3 |
| C _y | XTAL load capacitance | — | — | — | | 2, 3 |
| R _F | Feedback resistor — low-frequency, low-power mode (HGO=0) | — | — | — | MΩ | 2, 4 |
| | Feedback resistor — low-frequency, high-gain mode (HGO=1) | — | 10 | — | MΩ | |
| | Feedback resistor — high-frequency, low-power mode (HGO=0) | — | — | — | MΩ | |
| | Feedback resistor — high-frequency, high-gain mode (HGO=1) | — | 1 | — | MΩ | |
| R _S | Series resistor — low-frequency, low-power mode (HGO=0) | — | — | — | kΩ | |
| | Series resistor — low-frequency, high-gain mode (HGO=1) | — | 200 | — | kΩ | |
| | Series resistor — high-frequency, low-power mode (HGO=0) | — | — | — | kΩ | |
| | Series resistor — high-frequency, high-gain mode (HGO=1) | — | 0 | — | kΩ | |
| V _{pp} ⁵ | Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, low-power mode (HGO=0) | — | 0.6 | — | V | |
| | Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, high-gain mode (HGO=1) | — | V _{DD} | — | V | |
| | Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, low-power mode (HGO=0) | — | 0.6 | — | V | |
| | Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, high-gain mode (HGO=1) | — | V _{DD} | — | V | |

1. V_{DD}=3.3 V, Temperature =25 °C
2. See crystal or resonator manufacturer's recommendation
3. C_x,C_y can be provided by using either the integrated capacitors or by using external components.
4. When low power mode is selected, R_F is integrated and must not be attached externally.

5. The EXTAL and XTAL pins should only be connected to required oscillator components and must not be connected to any other devices.

6.3.2.2 Oscillator frequency specifications

Table 17. Oscillator frequency specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|------------------|---|------|------|------|------|-------|
| f_{osc_lo} | Oscillator crystal or resonator frequency — low frequency mode (MCG_C2[RANGE]=00) | 32 | — | 40 | kHz | |
| $f_{osc_hi_1}$ | Oscillator crystal or resonator frequency — high frequency mode (low range) (MCG_C2[RANGE]=01) | 3 | — | 8 | MHz | |
| $f_{osc_hi_2}$ | Oscillator crystal or resonator frequency — high frequency mode (high range) (MCG_C2[RANGE]=1x) | 8 | — | 32 | MHz | |
| f_{ec_extal} | Input clock frequency (external clock mode) | — | — | 50 | MHz | 1, 2 |
| t_{dc_extal} | Input clock duty cycle (external clock mode) | 40 | 50 | 60 | % | |
| t_{cst} | Crystal startup time — 32 kHz low-frequency, low-power mode (HGO=0) | — | 750 | — | ms | 3, 4 |
| | Crystal startup time — 32 kHz low-frequency, high-gain mode (HGO=1) | — | 250 | — | ms | |
| | Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), low-power mode (HGO=0) | — | 0.6 | — | ms | |
| | Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), high-gain mode (HGO=1) | — | 1 | — | ms | |

- Other frequency limits may apply when external clock is being used as a reference for the FLL or PLL.
- When transitioning from FBE to FEI mode, restrict the frequency of the input clock so that, when it is divided by FRDIV, it remains within the limits of the DCO input clock frequency.
- Proper PC board layout procedures must be followed to achieve specifications.
- Crystal startup time is defined as the time between the oscillator being enabled and the OSCINIT bit in the MCG_S register being set.

6.3.3 32kHz Oscillator Electrical Characteristics

This section describes the module electrical characteristics.

6.3.3.1 32kHz oscillator DC electrical specifications

Table 18. 32kHz oscillator DC electrical specifications

| Symbol | Description | Min. | Typ. | Max. | Unit |
|-----------|----------------------------|------|------|------|------|
| V_{BAT} | Supply voltage | 1.71 | — | 3.6 | V |
| R_F | Internal feedback resistor | — | 100 | — | MΩ |

Table continues on the next page...

Table 18. 32kHz oscillator DC electrical specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit |
|-----------------------|---|------|------|------|------|
| C_{para} | Parasitical capacitance of EXTAL32 and XTAL32 | — | 5 | 7 | pF |
| C_{load} | Internal load capacitance (programmable) | — | 15 | — | pF |
| V_{pp} ¹ | Peak-to-peak amplitude of oscillation | — | 0.6 | — | V |

1. The EXTAL32 and XTAL32 pins should only be connected to required oscillator components and must not be connected to any other devices.

6.3.3.2 32kHz oscillator frequency specifications

Table 19. 32kHz oscillator frequency specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---------------|-----------------------|------|--------|------|------|-------|
| f_{osc_lo} | Oscillator crystal | — | 32.768 | — | kHz | |
| t_{start} | Crystal start-up time | — | 1000 | — | ms | 1 |

1. Proper PC board layout procedures must be followed to achieve specifications.

6.4 Memories and memory interfaces

6.4.1 Flash (FTFL) electrical specifications

This section describes the electrical characteristics of the FTFL module.

6.4.1.1 Flash timing specifications — program and erase

The following specifications represent the amount of time the internal charge pumps are active and do not include command overhead.

Table 20. NVM program/erase timing specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|--------------------|--|------|------|------|---------|-------|
| t_{hvpgm4} | Longword Program high-voltage time | — | 7.5 | 18 | μ s | |
| $t_{hversscr}$ | Sector Erase high-voltage time | — | 13 | 113 | ms | 1 |
| $t_{hversblk256k}$ | Erase Block high-voltage time for 256 KB | — | 416 | 3616 | ms | 1 |

1. Maximum time based on expectations at cycling end-of-life.

6.4.1.2 Flash timing specifications — commands

Table 21. Flash command timing specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|------------------|---|------|------|------|---------|-------|
| $t_{rd1blk256k}$ | Read 1s Block execution time • 256 KB program/data flash | — | — | 1.7 | ms | |
| $t_{rd1sec2k}$ | Read 1s Section execution time (flash sector) | — | — | 60 | μ s | 1 |
| t_{pgmchk} | Program Check execution time | — | — | 45 | μ s | 1 |
| t_{rdsrc} | Read Resource execution time | — | — | 30 | μ s | 1 |
| t_{pgm4} | Program Longword execution time | — | 65 | 145 | μ s | |
| $t_{ersblk256k}$ | Erase Flash Block execution time • 256 KB program/data flash | — | 435 | 3700 | ms | 2 |
| t_{ersscr} | Erase Flash Sector execution time | — | 14 | 114 | ms | 2 |
| $t_{pgmsec512}$ | Program Section execution time • 512 B flash | — | 2.4 | — | ms | |
| $t_{pgmsec1k}$ | • 1 KB flash | — | 4.7 | — | ms | |
| $t_{pgmsec2k}$ | • 2 KB flash | — | 9.3 | — | ms | |
| t_{rd1all} | Read 1s All Blocks execution time | — | — | 1.8 | ms | |
| t_{rdonce} | Read Once execution time | — | — | 25 | μ s | 1 |
| $t_{pgmonce}$ | Program Once execution time | — | 65 | — | μ s | |
| t_{ersall} | Erase All Blocks execution time | — | 870 | 7400 | ms | 2 |
| t_{vfykey} | Verify Backdoor Access Key execution time | — | — | 30 | μ s | 1 |
| $t_{swapx01}$ | Swap Control execution time • control code 0x01 | — | 200 | — | μ s | |
| $t_{swapx02}$ | • control code 0x02 | — | 70 | 150 | μ s | |
| $t_{swapx04}$ | • control code 0x04 | — | 70 | 150 | μ s | |
| $t_{swapx08}$ | • control code 0x08 | — | — | 30 | μ s | |

1. Assumes 25MHz flash clock frequency.
2. Maximum times for erase parameters based on expectations at cycling end-of-life.

6.4.1.3 Flash (FTFL) current and power specifications

Table 22. Flash (FTFL) current and power specifications

| Symbol | Description | Typ. | Unit |
|---------------|---|------|------|
| I_{DD_PGM} | Worst case programming current in program flash | 10 | mA |

6.4.1.4 Reliability specifications

Table 23. NVM reliability specifications

| Symbol | Description | Min. | Typ. ¹ | Max. | Unit | Notes |
|--------------------------|--|------|-------------------|------|--------|-------|
| Program Flash | | | | | | |
| $t_{\text{nv mretp10k}}$ | Data retention after up to 10 K cycles | 5 | 50 | — | years | 2 |
| $t_{\text{nv mretp1k}}$ | Data retention after up to 1 K cycles | 10 | 100 | — | years | 2 |
| $t_{\text{nv mretp100}}$ | Data retention after up to 100 cycles | 15 | 100 | — | years | 2 |
| $n_{\text{nv mcycp}}$ | Cycling endurance | 10 K | 35 K | — | cycles | 3 |

1. Typical data retention values are based on measured response accelerated at high temperature and derated to a constant 25°C use profile. Engineering Bulletin EB618 does not apply to this technology.
2. Data retention is based on $T_{\text{javg}} = 55^\circ\text{C}$ (temperature profile over the lifetime of the application).
3. Cycling endurance represents number of program/erase cycles at $-40^\circ\text{C} \leq T_j \leq 125^\circ\text{C}$.

6.4.2 EzPort Switching Specifications

Table 24. EzPort switching specifications

| Num | Description | Min. | Max. | Unit |
|------|--|-------------------------------|--------------------|------|
| | Operating voltage | 1.71 | 3.6 | V |
| EP1 | EZP_CK frequency of operation (all commands except READ) | — | $f_{\text{SYS}}/2$ | MHz |
| EP1a | EZP_CK frequency of operation (READ command) | — | $f_{\text{SYS}}/8$ | MHz |
| EP2 | $\overline{\text{EZP_CS}}$ negation to next $\overline{\text{EZP_CS}}$ assertion | $2 \times t_{\text{EZP_CK}}$ | — | ns |
| EP3 | $\overline{\text{EZP_CS}}$ input valid to EZP_CK high (setup) | 5 | — | ns |
| EP4 | EZP_CK high to $\overline{\text{EZP_CS}}$ input invalid (hold) | 5 | — | ns |
| EP5 | EZP_D input valid to EZP_CK high (setup) | 2 | — | ns |
| EP6 | EZP_CK high to EZP_D input invalid (hold) | 5 | — | ns |
| EP7 | EZP_CK low to EZP_Q output valid | — | 16 | ns |
| EP8 | EZP_CK low to EZP_Q output invalid (hold) | 0 | — | ns |
| EP9 | $\overline{\text{EZP_CS}}$ negation to EZP_Q tri-state | — | 12 | ns |

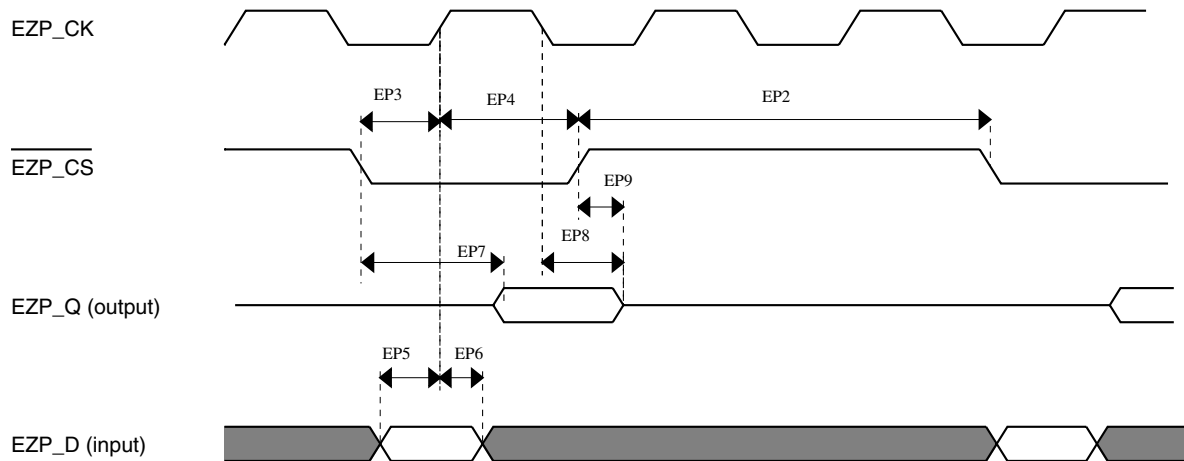


Figure 9. EzPort Timing Diagram

6.4.3 Flexbus Switching Specifications

All processor bus timings are synchronous; input setup/hold and output delay are given in respect to the rising edge of a reference clock, FB_CLK. The FB_CLK frequency may be the same as the internal system bus frequency or an integer divider of that frequency.

The following timing numbers indicate when data is latched or driven onto the external bus, relative to the Flexbus output clock (FB_CLK). All other timing relationships can be derived from these values.

Table 25. Flexbus limited voltage range switching specifications

| Num | Description | Min. | Max. | Unit | Notes |
|-----|---|------|--------|------|-------|
| | Operating voltage | 2.7 | 3.6 | V | |
| | Frequency of operation | — | FB_CLK | MHz | |
| FB1 | Clock period | 20 | — | ns | |
| FB2 | Address, data, and control output valid | — | 11.5 | ns | 1 |
| FB3 | Address, data, and control output hold | 0.5 | — | ns | 1 |
| FB4 | Data and $\overline{\text{FB_TA}}$ input setup | 8.5 | — | ns | 2 |
| FB5 | Data and $\overline{\text{FB_TA}}$ input hold | 0.5 | — | ns | 2 |

1. Specification is valid for all FB_AD[31:0], $\overline{\text{FB_BE/BWE}n}$, $\overline{\text{FB_CS}n}$, FB_OE, FB_R/W, FB_TBST, FB_TSIZ[1:0], FB_ALE, and $\overline{\text{FB_TS}}$.

Peripheral operating requirements and behaviors

2. Specification is valid for all FB_AD[31:0] and $\overline{\text{FB_TA}}$.

Table 26. Flexbus full voltage range switching specifications

| Num | Description | Min. | Max. | Unit | Notes |
|-----|---|----------|--------|------|-------|
| | Operating voltage | 1.71 | 3.6 | V | |
| | Frequency of operation | — | FB_CLK | MHz | |
| FB1 | Clock period | 1/FB_CLK | — | ns | |
| FB2 | Address, data, and control output valid | — | 13.5 | ns | 1 |
| FB3 | Address, data, and control output hold | 0 | — | ns | 1 |
| FB4 | Data and $\overline{\text{FB_TA}}$ input setup | 13.7 | — | ns | 2 |
| FB5 | Data and $\overline{\text{FB_TA}}$ input hold | 0.5 | — | ns | 2 |

1. Specification is valid for all FB_AD[31:0], FB_BE/BWE \overline{n} , FB_CS \overline{n} , FB_OE, FB_R/W, FB_TBST, FB_TSIZE[1:0], FB_ALE, and FB_TS.
2. Specification is valid for all FB_AD[31:0] and $\overline{\text{FB_TA}}$.

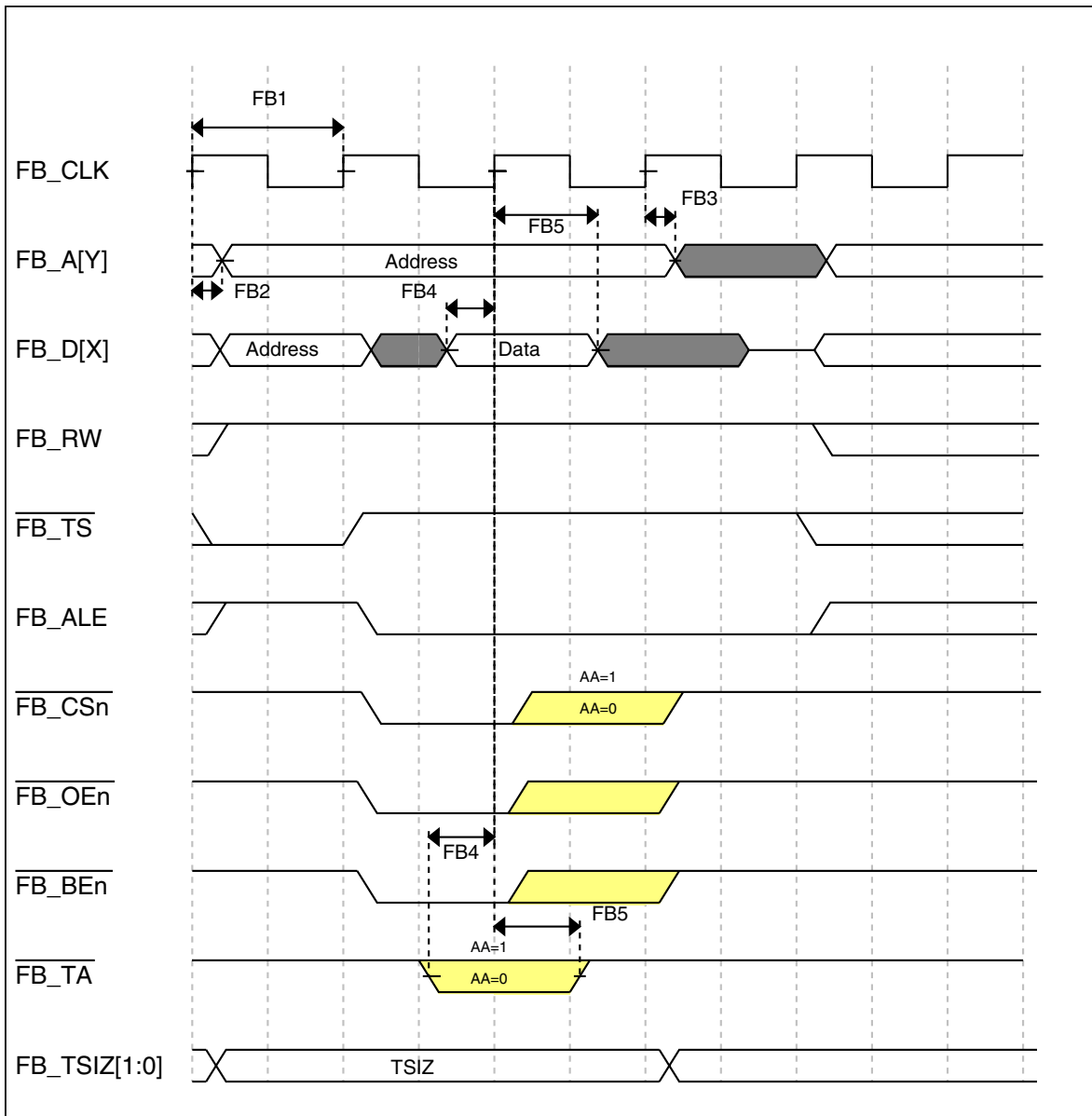


Figure 10. FlexBus read timing diagram

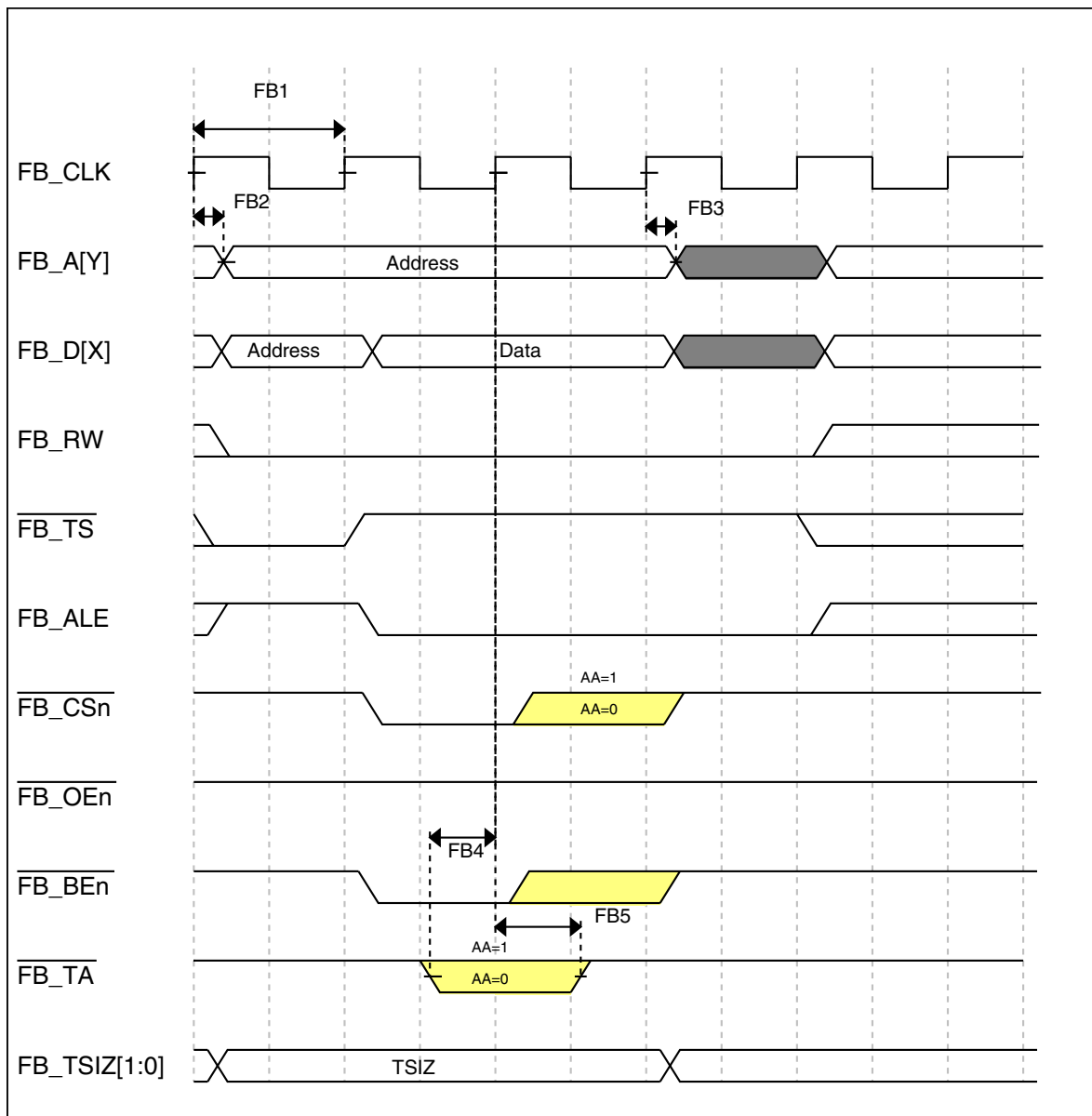


Figure 11. FlexBus write timing diagram

6.5 Security and integrity modules

There are no specifications necessary for the device's security and integrity modules.

6.6 Analog

6.6.1 ADC electrical specifications

The 16-bit accuracy specifications listed in [Table 27](#) and [Table 28](#) are achievable on the differential pins ADC_x_DP0, ADC_x_DM0, ADC_x_DP1, ADC_x_DM1, ADC_x_DP3, and ADC_x_DM3.

The ADC_x_DP2 and ADC_x_DM2 ADC inputs are connected to the PGA outputs and are not direct device pins. Accuracy specifications for these pins are defined in [Table 29](#) and [Table 30](#).

All other ADC channels meet the 13-bit differential/12-bit single-ended accuracy specifications.

6.6.1.1 16-bit ADC operating conditions

Table 27. 16-bit ADC operating conditions

| Symbol | Description | Conditions | Min. | Typ. ¹ | Max. | Unit | Notes |
|-------------------|--------------------------------|---|-------------------|-------------------|-------------------|------|-------|
| V _{DDA} | Supply voltage | Absolute | 1.71 | — | 3.6 | V | |
| ΔV _{DDA} | Supply voltage | Delta to V _{DD} (V _{DD} -V _{DDA}) | -100 | 0 | +100 | mV | 2 |
| ΔV _{SSA} | Ground voltage | Delta to V _{SS} (V _{SS} -V _{SSA}) | -100 | 0 | +100 | mV | 2 |
| V _{REFH} | ADC reference voltage high | | 1.13 | V _{DDA} | V _{DDA} | V | |
| V _{REFL} | Reference voltage low | | V _{SSA} | V _{SSA} | V _{SSA} | V | |
| V _{ADIN} | Input voltage | | V _{REFL} | — | V _{REFH} | V | |
| C _{ADIN} | Input capacitance | <ul style="list-style-type: none"> 16 bit modes 8/10/12 bit modes | — | 8 | 10 | pF | |
| R _{ADIN} | Input resistance | | — | 2 | 5 | kΩ | |
| R _{AS} | Analog source resistance | 13/12 bit modes f _{ADCK} < 4MHz | — | — | 5 | kΩ | 3 |
| f _{ADCK} | ADC conversion clock frequency | ≤ 13 bit modes | 1.0 | — | 18.0 | MHz | 4 |
| f _{ADCK} | ADC conversion clock frequency | 16 bit modes | 2.0 | — | 12.0 | MHz | 4 |

Table continues on the next page...

Table 27. 16-bit ADC operating conditions (continued)

| Symbol | Description | Conditions | Min. | Typ. ¹ | Max. | Unit | Notes |
|------------|---------------------|---|--------|-------------------|---------|------|-------|
| C_{rate} | ADC conversion rate | ≤ 13 bit modes No ADC hardware averaging Continuous conversions enabled, subsequent conversion time | 20.000 | — | 818.330 | Ksps | 5 |
| C_{rate} | ADC conversion rate | 16 bit modes No ADC hardware averaging Continuous conversions enabled, subsequent conversion time | 37.037 | — | 461.467 | Ksps | 5 |

1. Typical values assume $V_{DDA} = 3.0\text{ V}$, $\text{Temp} = 25^\circ\text{C}$, $f_{ADCK} = 1.0\text{ MHz}$ unless otherwise stated. Typical values are for reference only and are not tested in production.
2. DC potential difference.
3. This resistance is external to MCU. The analog source resistance should be kept as low as possible in order to achieve the best results. The results in this datasheet were derived from a system which has $<8\ \Omega$ analog source resistance. The R_{AS}/C_{AS} time constant should be kept to $<1\text{ ns}$.
4. To use the maximum ADC conversion clock frequency, the ADHSC bit should be set and the ADLPC bit should be clear.
5. For guidelines and examples of conversion rate calculation, download the ADC calculator tool: http://cache.freescale.com/files/soft_dev_tools/software/app_software/converters/ADC_CALCULATOR_CNV.zip?fp=1

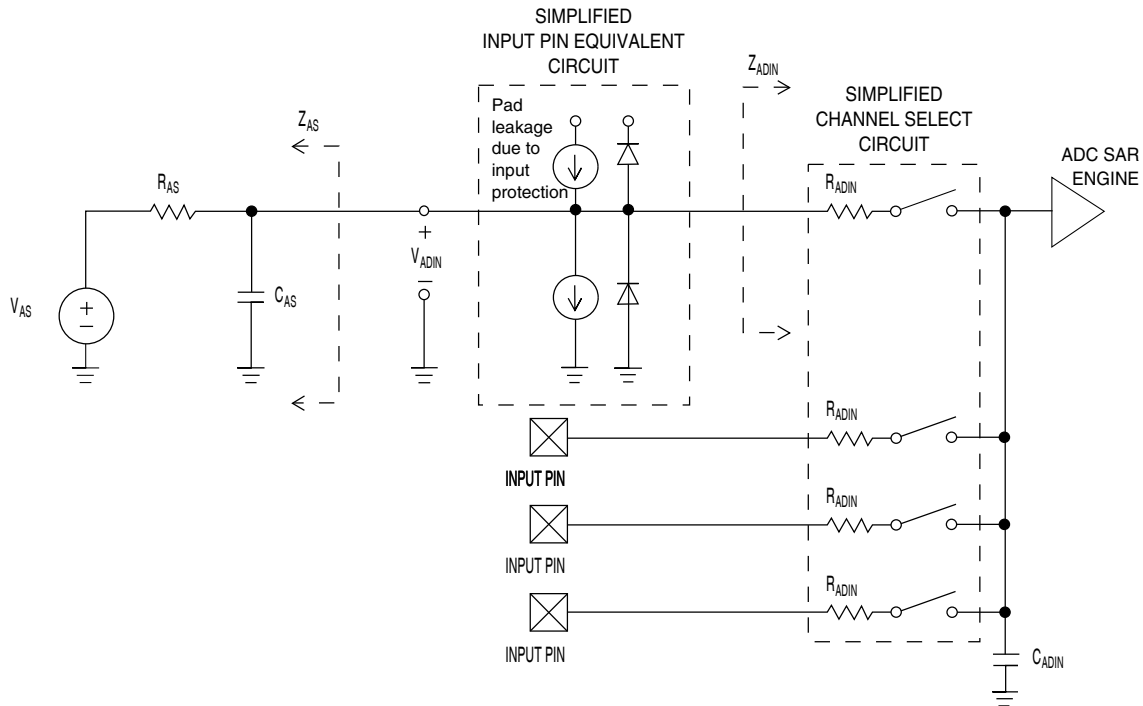


Figure 12. ADC input impedance equivalency diagram

6.6.1.2 16-bit ADC electrical characteristics

Table 28. 16-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$)

| Symbol | Description | Conditions ¹ | Min. | Typ. ² | Max. | Unit | Notes |
|----------------|---------------------------------|--|----------------------------------|----------------------------------|------------------------------|----------------------------------|---------------------------|
| I_{DDA_ADC} | Supply current | | 0.215 | — | 1.7 | mA | 3 |
| f_{ADACK} | ADC asynchronous clock source | • ADLPC=1, ADHSC=0 | 1.2 | 2.4 | 3.9 | MHz | $t_{ADACK} = 1/f_{ADACK}$ |
| | | • ADLPC=1, ADHSC=1 | 3.0 | 4.0 | 7.3 | MHz | |
| | | • ADLPC=0, ADHSC=0 | 2.4 | 5.2 | 6.1 | MHz | |
| | | • ADLPC=0, ADHSC=1 | 4.4 | 6.2 | 9.5 | MHz | |
| | Sample Time | See Reference Manual chapter for sample times | | | | | |
| TUE | Total unadjusted error | • 12 bit modes • <12 bit modes | — — | ± 4 ± 1.4 | ± 6.8 ± 2.1 | LSB ⁴ | 5 |
| DNL | Differential non-linearity | • 12 bit modes • <12 bit modes | — — | ± 0.7 ± 0.2 | -1.1 to +1.9 -0.3 to 0.5 | LSB ⁴ | 5 |
| INL | Integral non-linearity | • 12 bit modes • <12 bit modes | — — | ± 1.0 ± 0.5 | -2.7 to +1.9 -0.7 to +0.5 | LSB ⁴ | 5 |
| E_{FS} | Full-scale error | • 12 bit modes • <12 bit modes | — — | -4 -1.4 | -5.4 -1.8 | LSB ⁴ | $V_{ADIN} = V_{DDA}$ 5 |
| E_Q | Quantization error | • 16 bit modes • ≤ 13 bit modes | — — | -1 to 0 — | — ± 0.5 | LSB ⁴ | |
| ENOB | Effective number of bits | 16 bit differential mode • Avg=32 • Avg=4 16 bit single-ended mode • Avg=32 • Avg=4 | 12.8 11.9 12.2 11.4 | 14.5 13.8 13.9 13.1 | — — — — | bits bits bits bits | 6 |
| SINAD | Signal-to-noise plus distortion | See ENOB | 6.02 × ENOB + 1.76 | | | dB | |
| THD | Total harmonic distortion | 16 bit differential mode • Avg=32 16 bit single-ended mode • Avg=32 | — — | -94 -85 | — — | dB dB | 7 |

Table continues on the next page...

Table 28. 16-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$) (continued)

| Symbol | Description | Conditions ¹ | Min. | Typ. ² | Max. | Unit | Notes |
|---------------------|-----------------------------|--------------------------------------|------------------------|-------------------|------|-------|---|
| SFDR | Spurious free dynamic range | 16 bit differential mode • Avg=32 | 82 | 95 | — | dB | 7 |
| | | 16 bit single-ended mode • Avg=32 | 78 | 90 | — | dB | |
| E _{IL} | Input leakage error | | $I_{in} \times R_{AS}$ | | | mV | I _{in} = leakage current (refer to the MCU's voltage and current operating ratings) |
| | Temp sensor slope | −40°C to 105°C | — | 1.715 | — | mV/°C | |
| V _{TEMP25} | Temp sensor voltage | 25°C | — | 719 | — | mV | |

- All accuracy numbers assume the ADC is calibrated with $V_{REFH} = V_{DDA}$
- Typical values assume $V_{DDA} = 3.0$ V, Temp = 25°C, $f_{ADCK} = 2.0$ MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
- The ADC supply current depends on the ADC conversion clock speed, conversion rate and the ADLPC bit (low power). For lowest power operation the ADLPC bit should be set, the HSC bit should be clear with 1MHz ADC conversion clock speed.
- 1 LSB = $(V_{REFH} - V_{REFL})/2^N$
- ADC conversion clock <16MHz, Max hardware averaging (AVGE = %1, AVGS = %11)
- Input data is 100 Hz sine wave. ADC conversion clock <12MHz.
- Input data is 1 kHz sine wave. ADC conversion clock <12MHz.

Typical ADC 16-bit Differential ENOB vs ADC Clock
100Hz, 90% FS Sine Input

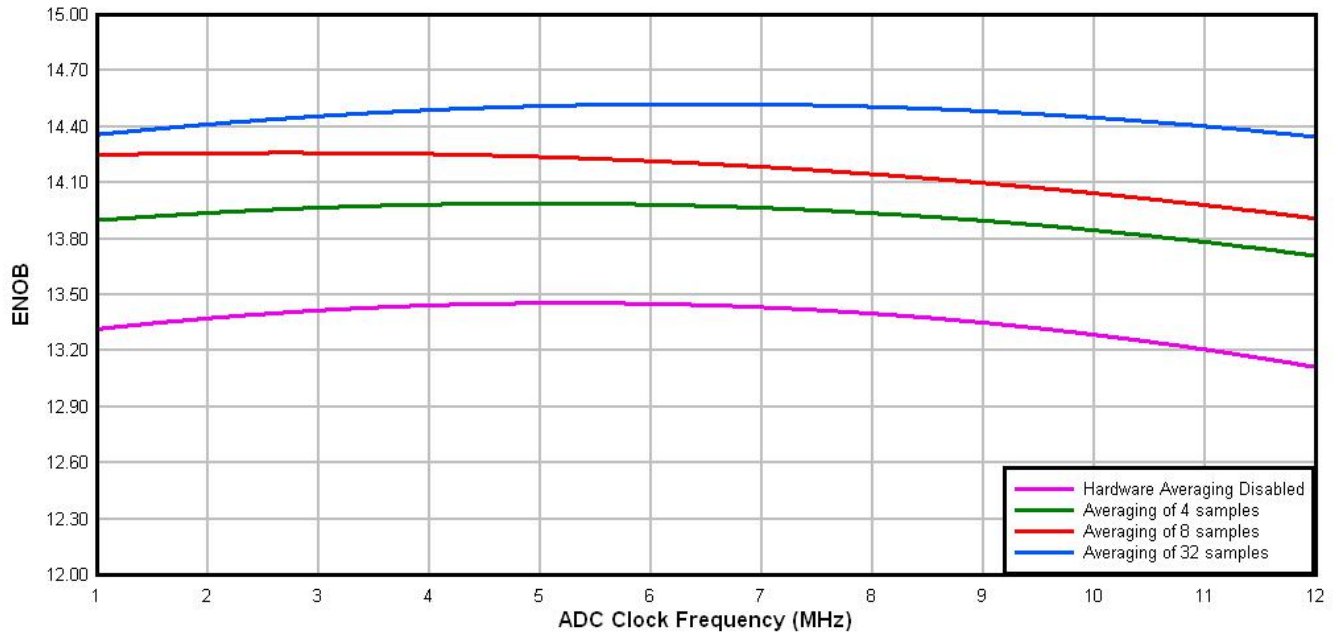


Figure 13. Typical ENOB vs. ADC_CLK for 16-bit differential mode

Typical ADC 16-bit Single-Ended ENOB vs ADC Clock
100Hz, 90% FS Sine Input

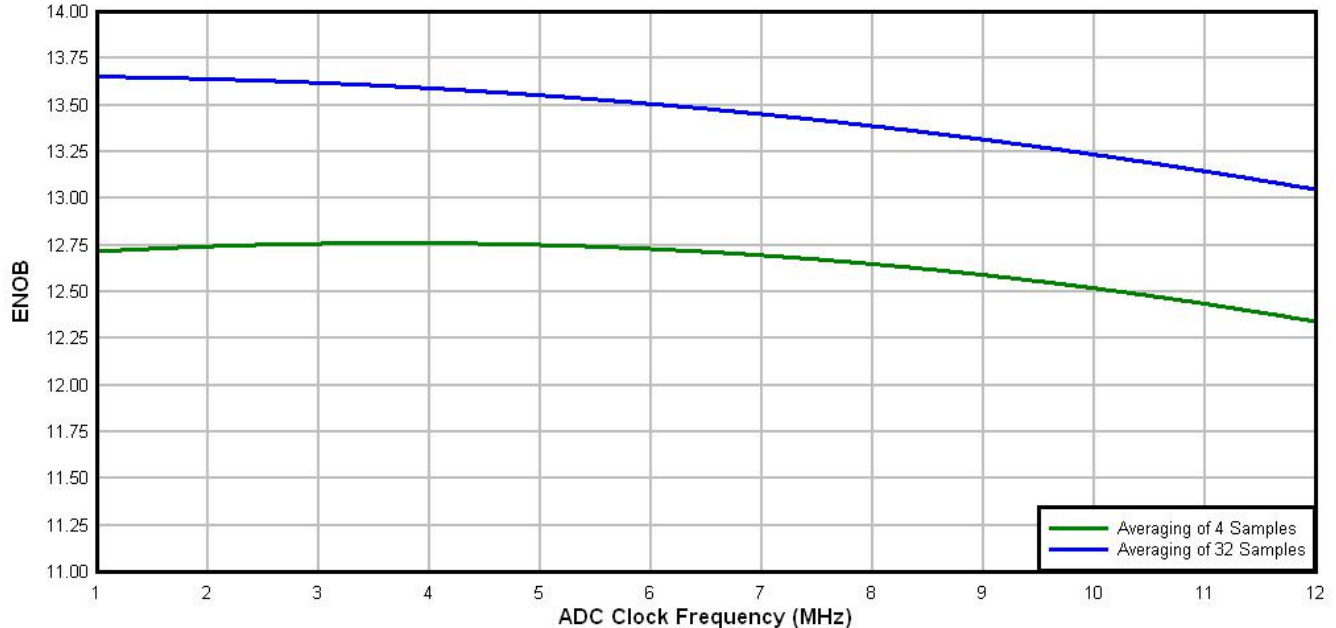


Figure 14. Typical ENOB vs. ADC_CLK for 16-bit single-ended mode

6.6.1.3 16-bit ADC with PGA operating conditions**Table 29. 16-bit ADC with PGA operating conditions**

| Symbol | Description | Conditions | Min. | Typ. ¹ | Max. | Unit | Notes |
|---------------------|------------------------------|--|------------------|-------------------|------------------|------|-------------------------|
| V _{DDA} | Supply voltage | Absolute | 1.71 | — | 3.6 | V | |
| V _{REFPGA} | PGA ref voltage | | VREF_OUT T | VREF_OUT T | VREF_OUT T | V | 2, 3 |
| V _{ADIN} | Input voltage | | V _{SSA} | — | V _{DDA} | V | |
| V _{CM} | Input Common Mode range | | V _{SSA} | — | V _{DDA} | V | |
| R _{PGAD} | Differential input impedance | Gain = 1, 2, 4, 8 Gain = 16, 32 Gain = 64 | — — — | 128 64 32 | — — — | kΩ | IN+ to IN- ⁴ |
| R _{AS} | Analog source resistance | | — | 100 | — | Ω | 5 |
| T _S | ADC sampling time | | 1.25 | — | — | μs | 6 |
| C _{rate} | ADC conversion rate | ≤ 13 bit modes No ADC hardware averaging Continuous conversions enabled Peripheral clock = 50 MHz | 18.484 | — | 450 | Ksps | 7 |
| | | 16 bit modes No ADC hardware averaging Continuous conversions enabled Peripheral clock = 50 MHz | 37.037 | — | 250 | Ksps | 8 |

1. Typical values assume V_{DDA} = 3.0 V, Temp = 25°C, f_{ADCK} = 6 MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
2. ADC must be configured to use the internal voltage reference (VREF_OUT)
3. PGA reference is internally connected to the VREF_OUT pin. If the user wishes to drive VREF_OUT with a voltage other than the output of the VREF module, the VREF module must be disabled.
4. For single ended configurations the input impedance of the driven input is R_{PGAD}/2
5. The analog source resistance (R_{AS}), external to MCU, should be kept as minimum as possible. Increased R_{AS} causes drop in PGA gain without affecting other performances. This is not dependent on ADC clock frequency.
6. The minimum sampling time is dependent on input signal frequency and ADC mode of operation. A minimum of 1.25μs time should be allowed for F_{in}=4 kHz at 16-bit differential mode. Recommended ADC setting is: ADLSMP=1, ADLSTS=2 at 8 MHz ADC clock.
7. ADC clock = 18 MHz, ADLSMP = 1, ADLST = 00, ADHSC = 1
8. ADC clock = 12 MHz, ADLSMP = 1, ADLST = 01, ADHSC = 1

6.6.1.4 16-bit ADC with PGA characteristics

Table 30. 16-bit ADC with PGA characteristics

| Symbol | Description | Conditions | Min. | Typ. ¹ | Max. | Unit | Notes |
|----------------------|---|---|--|-------------------|------|------|---|
| I _{DDA_PGA} | Supply current | Low power (ADC_PGA[PGALPb]=0) | — | 420 | 644 | μA | 2 |
| I _{DC_PGA} | Input DC current | | $\frac{2}{R_{PGAD}} \left(\frac{V_{REFPGA} \times 0.583 - V_{CM}}{\text{Gain} + 1} \right)$ | | | A | 3 |
| | | Gain =1, V _{REFPGA} =1.2V, V _{CM} =0.5V | — | 1.54 | — | μA | |
| | | Gain =64, V _{REFPGA} =1.2V, V _{CM} =0.1V | — | 0.57 | — | μA | |
| G | Gain ⁴ | • PGAG=0 | 0.95 | 1 | 1.05 | | R _{AS} < 100Ω |
| | | • PGAG=1 | 1.9 | 2 | 2.1 | | |
| | | • PGAG=2 | 3.8 | 4 | 4.2 | | |
| | | • PGAG=3 | 7.6 | 8 | 8.4 | | |
| | | • PGAG=4 | 15.2 | 16 | 16.6 | | |
| | | • PGAG=5 | 30.0 | 31.6 | 33.2 | | |
| | | • PGAG=6 | 58.8 | 63.3 | 67.8 | | |
| BW | Input signal bandwidth | • 16-bit modes | — | — | 4 | kHz | |
| | | • < 16-bit modes | — | — | 40 | kHz | |
| PSRR | Power supply rejection ratio | Gain=1 | — | -84 | — | dB | V _{DDA} = 3V ±100mV, f _{VDDA} = 50Hz, 60Hz |
| CMRR | Common mode rejection ratio | • Gain=1 | — | -84 | — | dB | V _{CM} = 500mVpp, f _{VCM} = 50Hz, 100Hz |
| | | • Gain=64 | — | -85 | — | dB | |
| V _{OFS} | Input offset voltage | | — | 0.2 | — | mV | Output offset = V _{OFS} *(Gain+1) |
| T _{GSW} | Gain switching settling time | | — | — | 10 | μs | 5 |
| E _{IL} | Input leakage error | All modes | I _{In} × R _{AS} | | | mV | I _{In} = leakage current (refer to the MCU's voltage and current operating ratings) |
| V _{PP,DIFF} | Maximum differential input signal swing | | $\left(\frac{(\min(V_X, V_{DDA} - V_X) - 0.2) \times 4}{\text{Gain}} \right)$ where V _X = V _{REFPGA} × 0.583 | | | V | 6 |

Table continues on the next page...

Table 30. 16-bit ADC with PGA characteristics (continued)

| Symbol | Description | Conditions | Min. | Typ. ¹ | Max. | Unit | Notes |
|--------|---------------------------------------|--|--|---|---|--|---|
| SNR | Signal-to-noise ratio | <ul style="list-style-type: none"> Gain=1 Gain=64 | 80 52 | 90 66 | — — | dB dB | 16-bit differential mode, Average=32 |
| THD | Total harmonic distortion | <ul style="list-style-type: none"> Gain=1 Gain=64 | 85 49 | 100 95 | — — | dB dB | 16-bit differential mode, Average=32, $f_{in}=100\text{Hz}$ |
| SFDR | Spurious free dynamic range | <ul style="list-style-type: none"> Gain=1 Gain=64 | 85 53 | 105 88 | — — | dB dB | 16-bit differential mode, Average=32, $f_{in}=100\text{Hz}$ |
| ENOB | Effective number of bits | <ul style="list-style-type: none"> Gain=1, Average=4 Gain=64, Average=4 Gain=1, Average=32 Gain=2, Average=32 Gain=4, Average=32 Gain=8, Average=32 Gain=16, Average=32 Gain=32, Average=32 Gain=64, Average=32 | 11.6 7.2 12.8 11.0 7.9 7.3 6.8 6.8 7.5 | 13.4 9.6 14.5 14.3 13.8 13.1 12.5 11.5 10.6 | — — — — — — — — — | bits bits bits bits bits bits bits bits bits | 16-bit differential mode, $f_{in}=100\text{Hz}$ |
| SINAD | Signal-to-noise plus distortion ratio | See ENOB | 6.02 × ENOB + 1.76 | | | dB | |

1. Typical values assume $V_{DDA}=3.0\text{V}$, $\text{Temp}=25^{\circ}\text{C}$, $f_{ADCK}=6\text{MHz}$ unless otherwise stated.
2. This current is a PGA module adder, in addition to and ADC conversion currents.
3. Between IN+ and IN-. The PGA draws a DC current from the input terminals. The magnitude of the DC current is a strong function of input common mode voltage (V_{CM}) and the PGA gain.
4. $\text{Gain} = 2^{\text{PGA}}$
5. After changing the PGA gain setting, a minimum of 2 ADC+PGA conversions should be ignored.
6. Limit the input signal swing so that the PGA does not saturate during operation. Input signal swing is dependent on the PGA reference voltage and gain setting.

6.6.2 CMP and 6-bit DAC electrical specifications

Table 31. Comparator and 6-bit DAC electrical specifications

| Symbol | Description | Min. | Typ. | Max. | Unit |
|------------|---|------|------|------|---------------|
| V_{DD} | Supply voltage | 1.71 | — | 3.6 | V |
| I_{DDHS} | Supply current, High-speed mode (EN=1, PMODE=1) | — | — | 200 | μA |

Table continues on the next page...

Table 31. Comparator and 6-bit DAC electrical specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit |
|-------------|---|----------------|------|----------|------------------|
| I_{DDL5} | Supply current, low-speed mode (EN=1, PMODE=0) | — | — | 20 | μA |
| V_{AIN} | Analog input voltage | $V_{SS} - 0.3$ | — | V_{DD} | V |
| V_{AIO} | Analog input offset voltage | — | — | 20 | mV |
| V_H | Analog comparator hysteresis ¹ | | | | |
| | • CR0[HYSTCTR] = 00 | — | 5 | — | mV |
| | • CR0[HYSTCTR] = 01 | — | 10 | — | mV |
| | • CR0[HYSTCTR] = 10 | — | 20 | — | mV |
| | • CR0[HYSTCTR] = 11 | — | 30 | — | mV |
| V_{CMPOH} | Output high | $V_{DD} - 0.5$ | — | — | V |
| V_{CMPOI} | Output low | — | — | 0.5 | V |
| t_{DHS} | Propagation delay, high-speed mode (EN=1, PMODE=1) | 20 | 50 | 200 | ns |
| t_{DLS} | Propagation delay, low-speed mode (EN=1, PMODE=0) | 120 | 250 | 600 | ns |
| | Analog comparator initialization delay ² | — | — | 40 | μs |
| I_{DAC6b} | 6-bit DAC current adder (enabled) | — | 7 | — | μA |
| INL | 6-bit DAC integral non-linearity | -0.5 | — | 0.5 | LSB ³ |
| DNL | 6-bit DAC differential non-linearity | -0.3 | — | 0.3 | LSB |

1. Typical hysteresis is measured with input voltage range limited to 0.6 to $V_{DD}-0.6\text{V}$.
2. Comparator initialization delay is defined as the time between software writes to change control inputs (Writes to DACEN, VRSEL, PSEL, MSEL, VOSEL) and the comparator output settling to a stable level.
3. $1 \text{ LSB} = V_{\text{reference}}/64$

Peripheral operating requirements and behaviors

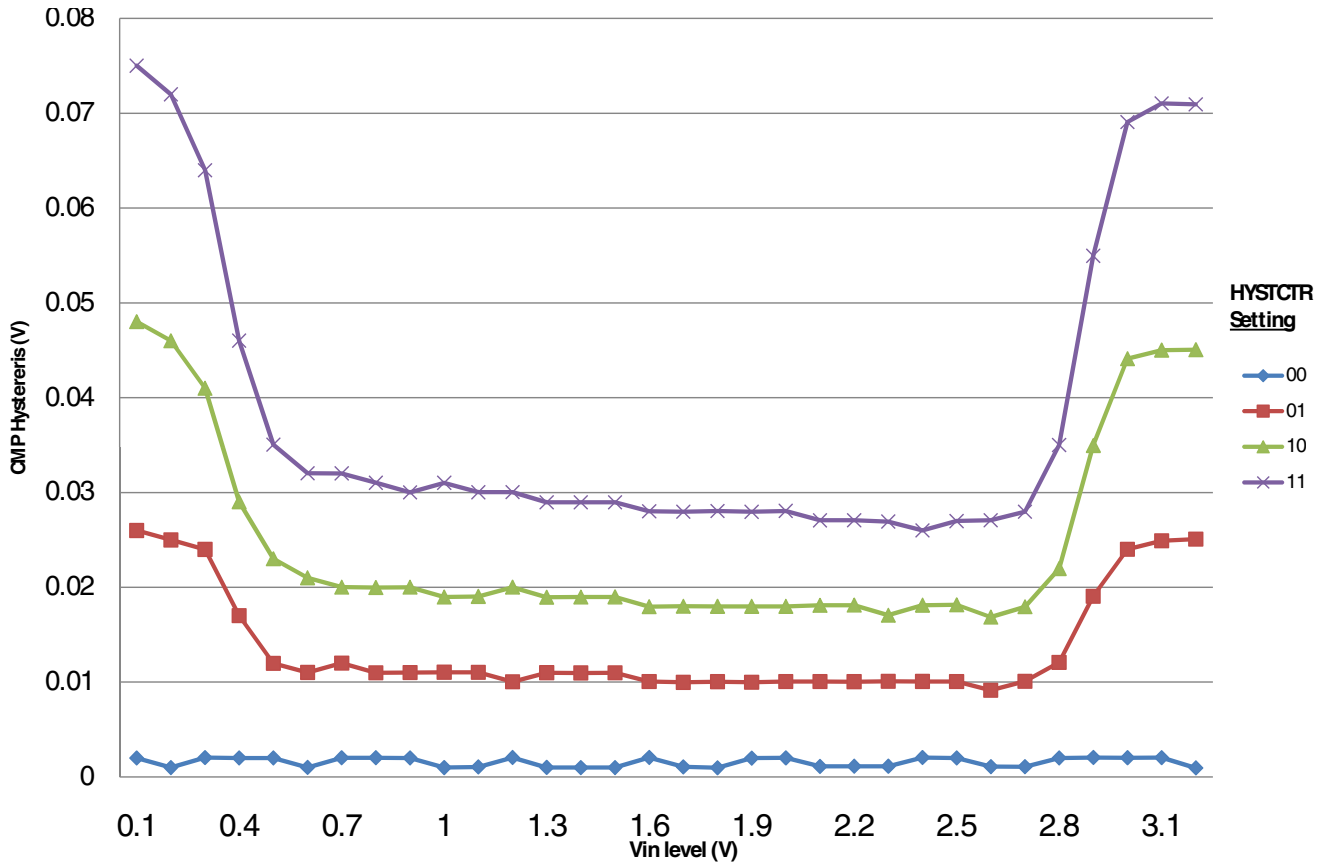


Figure 15. Typical hysteresis vs. Vin level (VDD=3.3V, PMODE=0)

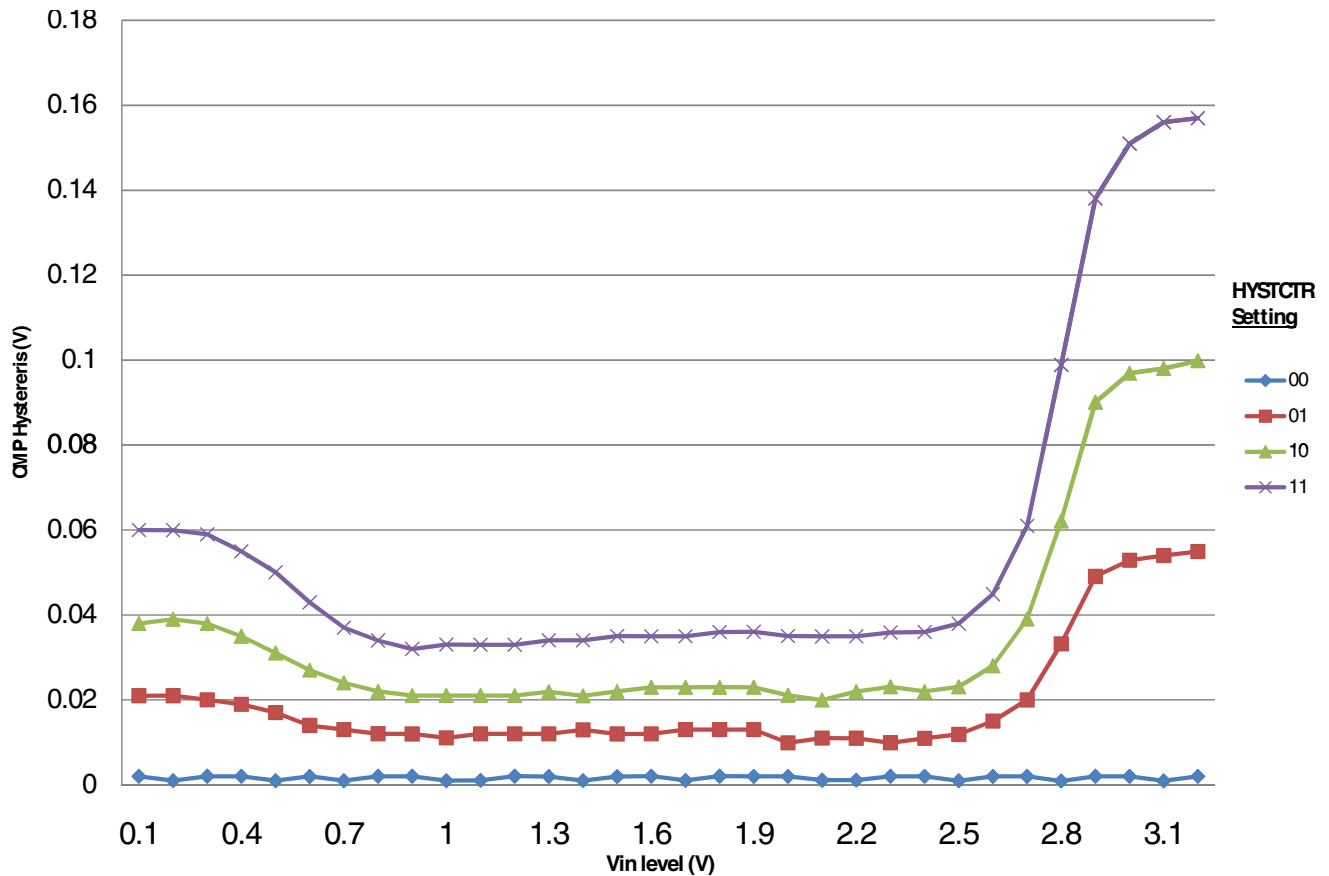


Figure 16. Typical hysteresis vs. Vin level (VDD=3.3V, PMODE=1)

6.6.3 12-bit DAC electrical characteristics

6.6.3.1 12-bit DAC operating requirements

Table 32. 12-bit DAC operating requirements

| Symbol | Description | Min. | Max. | Unit | Notes |
|------------|-------------------------|------|------|------|-------|
| V_{DDA} | Supply voltage | 1.71 | 3.6 | V | |
| V_{DACR} | Reference voltage | 1.13 | 3.6 | V | 1 |
| T_A | Temperature | -40 | 105 | °C | |
| C_L | Output load capacitance | — | 100 | pF | 2 |
| I_L | Output load current | — | 1 | mA | |

1. The DAC reference can be selected to be V_{DDA} or the voltage output of the VREF module (VREF_OUT)
2. A small load capacitance (47 pF) can improve the bandwidth performance of the DAC

6.6.3.2 12-bit DAC operating behaviors

Table 33. 12-bit DAC operating behaviors

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|--------------------|---|------------------|-------------|------------|------------------------|-------|
| $I_{DDA_DACL_P}$ | Supply current — low-power mode | — | — | 150 | μA | |
| $I_{DDA_DAC_HP}$ | Supply current — high-speed mode | — | — | 700 | μA | |
| t_{DACLP} | Full-scale settling time (0x080 to 0xF7F) — low-power mode | — | 100 | 200 | μs | 1 |
| t_{DACHP} | Full-scale settling time (0x080 to 0xF7F) — high-power mode | — | 15 | 30 | μs | 1 |
| $t_{CCDACLP}$ | Code-to-code settling time (0xBF8 to 0xC08) — low-power mode and high-speed mode | — | 0.7 | 1 | μs | 1 |
| $V_{dacoutl}$ | DAC output voltage range low — high-speed mode, no load, DAC set to 0x000 | — | — | 100 | mV | |
| $V_{dacouth}$ | DAC output voltage range high — high-speed mode, no load, DAC set to 0xFFF | $V_{DACR} - 100$ | — | V_{DACR} | mV | |
| INL | Integral non-linearity error — high speed mode | — | — | ± 8 | LSB | 2 |
| DNL | Differential non-linearity error — $V_{DACR} > 2\text{ V}$ | — | — | ± 1 | LSB | 3 |
| DNL | Differential non-linearity error — $V_{DACR} = V_{REF_OUT}$ | — | — | ± 1 | LSB | 4 |
| V_{OFFSET} | Offset error | — | ± 0.4 | ± 0.8 | %FSR | 5 |
| E_G | Gain error | — | ± 0.1 | ± 0.6 | %FSR | 5 |
| PSRR | Power supply rejection ratio, $V_{DDA} > = 2.4\text{ V}$ | 60 | — | 90 | dB | |
| T_{CO} | Temperature coefficient offset voltage | — | 3.7 | — | $\mu\text{V}/\text{C}$ | 6 |
| T_{GE} | Temperature coefficient gain error | — | 0.000421 | — | %FSR/C | |
| R_{op} | Output resistance load = 3 k Ω | — | — | 250 | Ω | |
| SR | Slew rate -80h \rightarrow F7Fh \rightarrow 80h <ul style="list-style-type: none"> • High power (SP_{HP}) • Low power (SP_{LP}) | 1.2 0.05 | 1.7 0.12 | — — | V/ μs | |
| CT | Channel to channel cross talk | — | — | -80 | dB | |
| BW | 3dB bandwidth <ul style="list-style-type: none"> • High power (SP_{HP}) • Low power (SP_{LP}) | 550 40 | — — | — — | kHz | |

1. Settling within ± 1 LSB
2. The INL is measured for 0+100mV to $V_{DACR} - 100\text{ mV}$
3. The DNL is measured for 0+100 mV to $V_{DACR} - 100\text{ mV}$
4. The DNL is measured for 0+100mV to $V_{DACR} - 100\text{ mV}$ with $V_{DDA} > 2.4\text{V}$
5. Calculated by a best fit curve from $V_{SS} + 100\text{ mV}$ to $V_{DACR} - 100\text{ mV}$

6. VDDA = 3.0V, reference select set for VDDA (DACx_CO:DACRFS = 1), high power mode(DACx_C0:LPEN = 0), DAC set to 0x800, Temp range from -40C to 105C

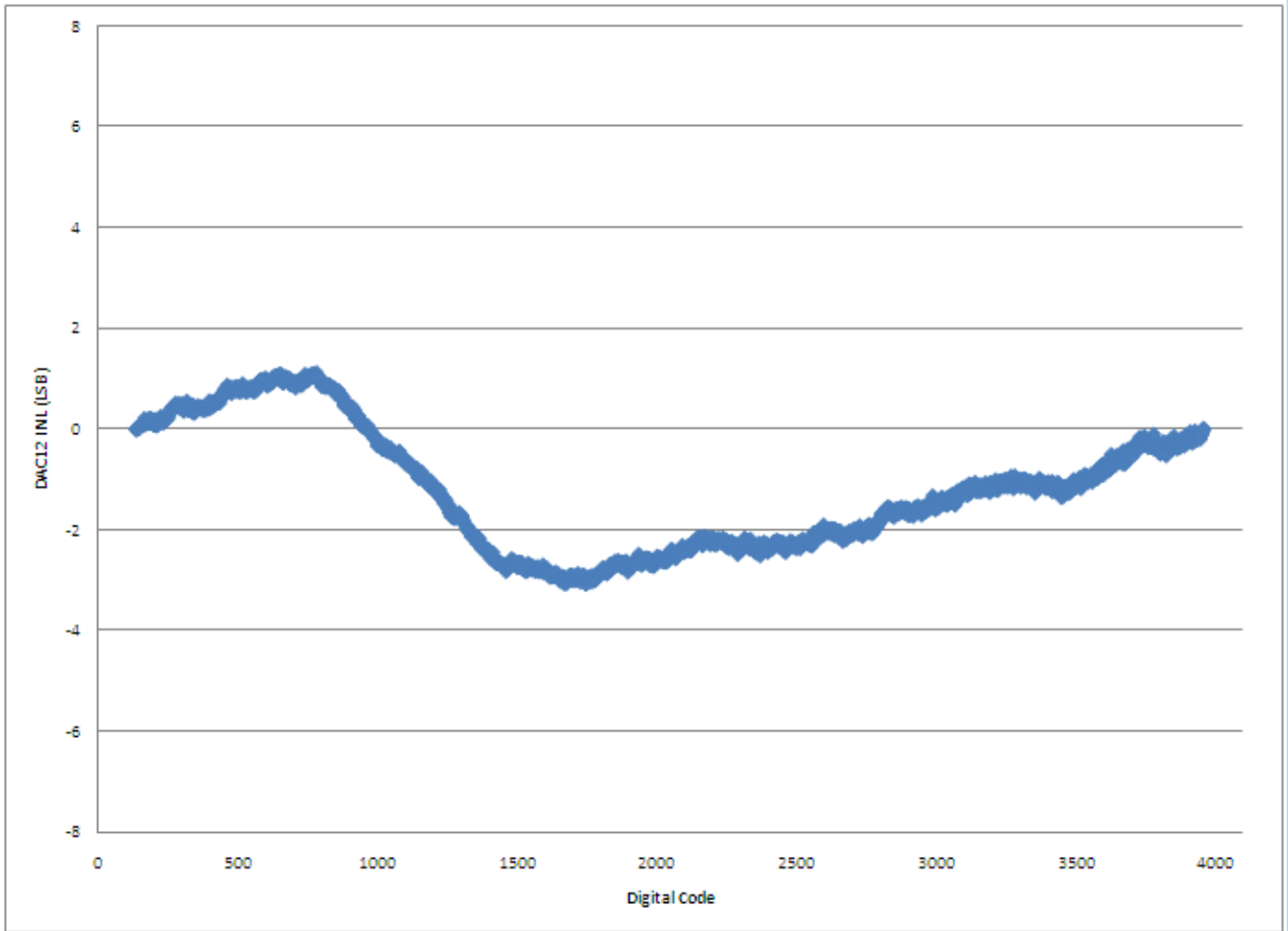


Figure 17. Typical INL error vs. digital code

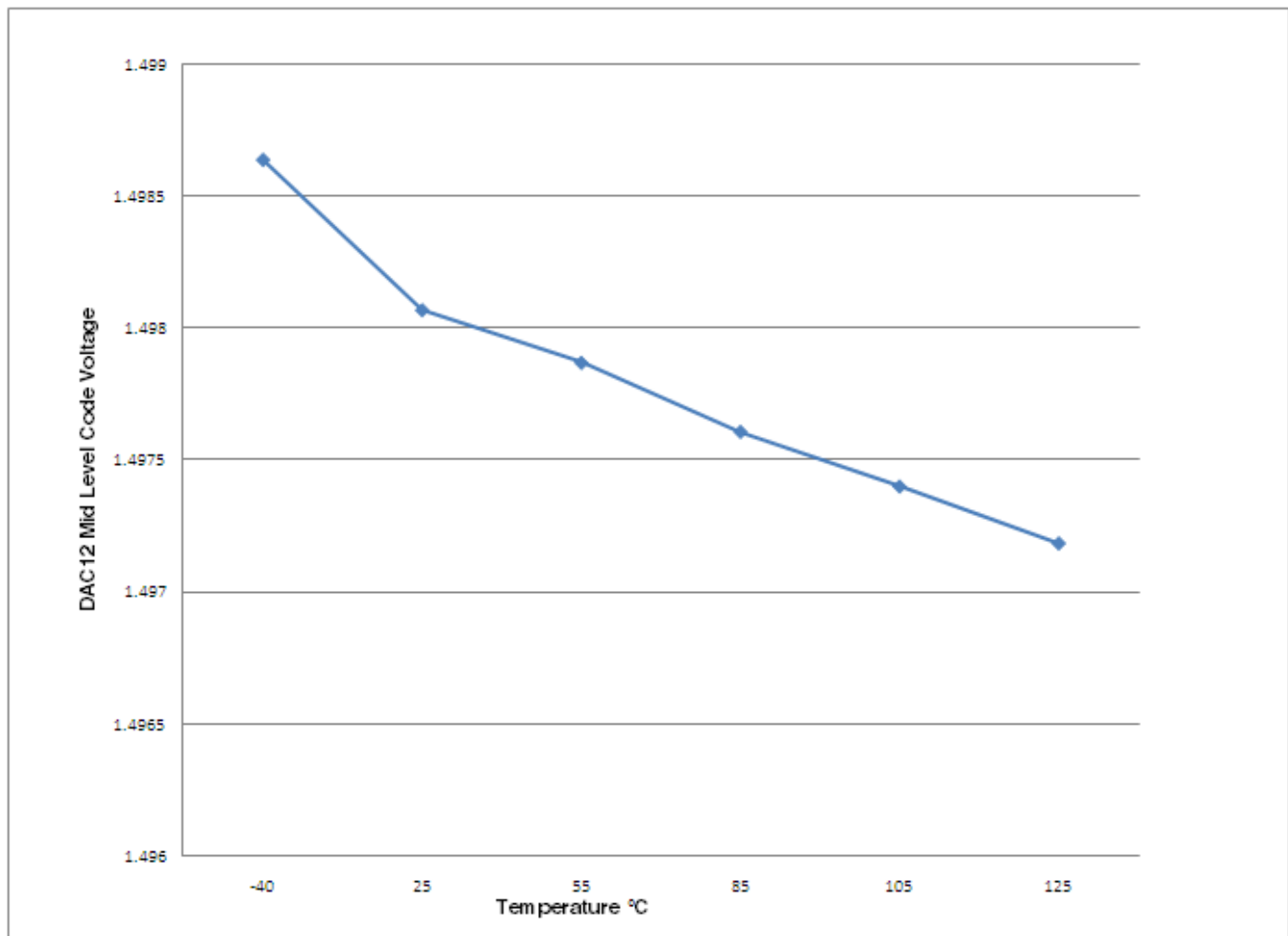


Figure 18. Offset at half scale vs. temperature

6.6.4 Voltage reference electrical specifications

Table 34. VREF full-range operating requirements

| Symbol | Description | Min. | Max. | Unit | Notes |
|-----------|-------------------------|------|------|------|-------|
| V_{DDA} | Supply voltage | 1.71 | 3.6 | V | |
| T_A | Temperature | -40 | 105 | °C | |
| C_L | Output load capacitance | 100 | | nF | 1 |

1. C_L must be connected to VREF_OUT if the VREF_OUT functionality is being used for either an internal or external reference.

Table 35. VREF full-range operating behaviors

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-------------------|---|--------|--------|--------|---------|-------|
| V_{out} | Voltage reference output with factory trim at nominal V_{DDA} and temperature=25C | 1.1965 | 1.2 | 1.2027 | V | |
| V_{out} | Voltage reference output with— factory trim | 1.1584 | — | 1.2376 | V | |
| V_{step} | Voltage reference trim step | — | 0.5 | — | mV | |
| V_{tdrift} | Temperature drift ($V_{max} - V_{min}$ across the full temperature range) | — | — | 80 | mV | |
| I_{bg} | Bandgap only (MODE_LV = 00) current | — | — | 80 | μ A | |
| I_{tr} | Tight-regulation buffer (MODE_LV =10) current | — | — | 1.1 | mA | |
| ΔV_{LOAD} | Load regulation (MODE_LV = 10) <ul style="list-style-type: none"> • current = + 1.0 mA • current = - 1.0 mA | — — | 2 5 | — — | mV | 1 |
| T_{stap} | Buffer startup time | — | — | 100 | μ s | |
| V_{vdrift} | Voltage drift ($V_{max} - V_{min}$ across the full voltage range) (MODE_LV = 10, REGEN = 1) | — | 2 | — | mV | |

1. Load regulation voltage is the difference between the VREF_OUT voltage with no load vs. voltage with defined load

Table 36. VREF limited-range operating requirements

| Symbol | Description | Min. | Max. | Unit | Notes |
|--------|-------------|------|------|--------------|-------|
| T_A | Temperature | 0 | 50 | $^{\circ}$ C | |

Table 37. VREF limited-range operating behaviors

| Symbol | Description | Min. | Max. | Unit | Notes |
|-----------|--|-------|-------|------|-------|
| V_{out} | Voltage reference output with factory trim | 1.173 | 1.225 | V | |

6.7 Timers

See [General switching specifications](#).

6.8 Communication interfaces

6.8.1 USB electrical specifications

The USB electricals for the USB On-the-Go module conform to the standards documented by the Universal Serial Bus Implementers Forum. For the most up-to-date standards, visit <http://www.usb.org>.

6.8.2 USB DCD electrical specifications

Table 38. USB DCD electrical specifications

| Symbol | Description | Min. | Typ. | Max. | Unit |
|----------------------|--|-------|------|------|------------|
| V _{DP_SRC} | USB_DP source voltage (up to 250 μ A) | 0.5 | — | 0.7 | V |
| V _{LGC} | Threshold voltage for logic high | 0.8 | — | 2.0 | V |
| I _{DP_SRC} | USB_DP source current | 7 | 10 | 13 | μ A |
| I _{DM_SINK} | USB_DM sink current | 50 | 100 | 150 | μ A |
| R _{DM_DWN} | D- pulldown resistance for data pin contact detect | 14.25 | — | 24.8 | k Ω |
| V _{DAT_REF} | Data detect voltage | 0.25 | 0.33 | 0.4 | V |

6.8.3 USB VREG electrical specifications

Table 39. USB VREG electrical specifications

| Symbol | Description | Min. | Typ. ¹ | Max. | Unit | Notes |
|-----------------------|--|------|-------------------|------|---------|-------|
| V _{REGIN} | Input supply voltage | 2.7 | — | 5.5 | V | |
| I _{DDon} | Quiescent current — Run mode, load current equal zero, input supply (V _{REGIN}) > 3.6 V | — | 120 | 186 | μ A | |
| I _{DDstby} | Quiescent current — Standby mode, load current equal zero | — | 1.27 | 30 | μ A | |
| I _{DDoff} | Quiescent current — Shutdown mode <ul style="list-style-type: none"> V_{REGIN} = 5.0 V and temperature=25C Across operating voltage and temperature | — | 650 | — | nA | |
| | | — | — | 4 | μ A | |
| I _{LOADrun} | Maximum load current — Run mode | — | — | 120 | mA | |
| I _{LOADstby} | Maximum load current — Standby mode | — | — | 1 | mA | |
| V _{Reg33out} | Regulator output voltage — Input supply (V _{REGIN}) > 3.6 V <ul style="list-style-type: none"> Run mode Standby mode | 3 | 3.3 | 3.6 | V | |
| | | 2.1 | 2.8 | 3.6 | V | |
| V _{Reg33out} | Regulator output voltage — Input supply (V _{REGIN}) < 3.6 V, pass-through mode | 2.1 | — | 3.6 | V | 2 |

Table continues on the next page...

**Table 39. USB VREG electrical specifications
(continued)**

| Symbol | Description | Min. | Typ. ¹ | Max. | Unit | Notes |
|------------------|--|------|-------------------|------|------|-------|
| C _{OUT} | External output capacitor | 1.76 | 2.2 | 8.16 | μF | |
| ESR | External output capacitor equivalent series resistance | 1 | — | 100 | mΩ | |
| I _{LIM} | Short circuit current | — | 290 | — | mA | |

1. Typical values assume VREGIN = 5.0 V, Temp = 25 °C unless otherwise stated.
2. Operating in pass-through mode: regulator output voltage equal to the input voltage minus a drop proportional to I_{Load}.

6.8.4 CAN switching specifications

See [General switching specifications](#).

6.8.5 DSPI switching specifications (limited voltage range)

The DMA Serial Peripheral Interface (DSPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The tables below provide DSPI timing characteristics for classic SPI timing modes. Refer to the DSPI chapter of the Reference Manual for information on the modified transfer formats used for communicating with slower peripheral devices.

Table 40. Master mode DSPI timing (limited voltage range)

| Num | Description | Min. | Max. | Unit | Notes |
|-----|---|----------------------------|---------------------------|------|-------|
| | Operating voltage | 2.7 | 3.6 | V | |
| | Frequency of operation | — | 25 | MHz | |
| DS1 | DSPI_SCK output cycle time | 2 × t _{BUS} | — | ns | |
| DS2 | DSPI_SCK output high/low time | (t _{SCK} /2) – 2 | (t _{SCK} /2) + 2 | ns | |
| DS3 | DSPI_PCS _n valid to DSPI_SCK delay | (t _{BUS} × 2) – 2 | — | ns | 1 |
| DS4 | DSPI_SCK to DSPI_PCS _n invalid delay | (t _{BUS} × 2) – 2 | — | ns | 2 |
| DS5 | DSPI_SCK to DSPI_SOUT valid | — | 8.5 | ns | |
| DS6 | DSPI_SCK to DSPI_SOUT invalid | –2 | — | ns | |
| DS7 | DSPI_SIN to DSPI_SCK input setup | 15 | — | ns | |
| DS8 | DSPI_SCK to DSPI_SIN input hold | 0 | — | ns | |

1. The delay is programmable in SPIx_CTARn[PSSCK] and SPIx_CTARn[CSSCK].
2. The delay is programmable in SPIx_CTARn[PASC] and SPIx_CTARn[ASC].

Peripheral operating requirements and behaviors

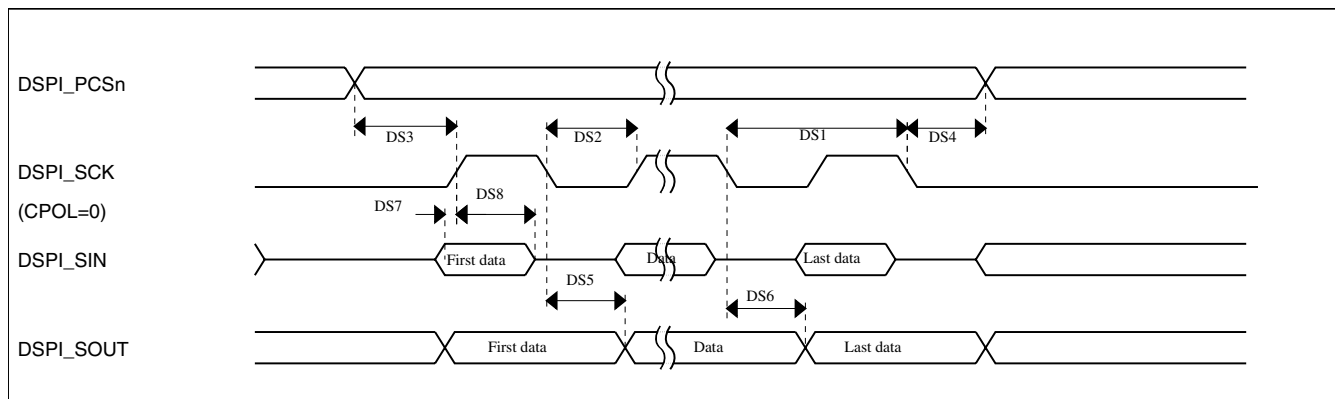


Figure 19. DSPI classic SPI timing — master mode

Table 41. Slave mode DSPI timing (limited voltage range)

| Num | Description | Min. | Max. | Unit |
|------|---|---------------------------|---------------------------|------|
| | Operating voltage | 2.7 | 3.6 | V |
| | Frequency of operation | | 12.5 | MHz |
| DS9 | DSPI_SCK input cycle time | 4 x t _{BUS} | — | ns |
| DS10 | DSPI_SCK input high/low time | (t _{SCK} /2) - 2 | (t _{SCK} /2) + 2 | ns |
| DS11 | DSPI_SCK to DSPI_SOUT valid | — | 10 | ns |
| DS12 | DSPI_SCK to DSPI_SOUT invalid | 0 | — | ns |
| DS13 | DSPI_SIN to DSPI_SCK input setup | 2 | — | ns |
| DS14 | DSPI_SCK to DSPI_SIN input hold | 7 | — | ns |
| DS15 | $\overline{\text{DSPI_SS}}$ active to DSPI_SOUT driven | — | 14 | ns |
| DS16 | $\overline{\text{DSPI_SS}}$ inactive to DSPI_SOUT not driven | — | 14 | ns |

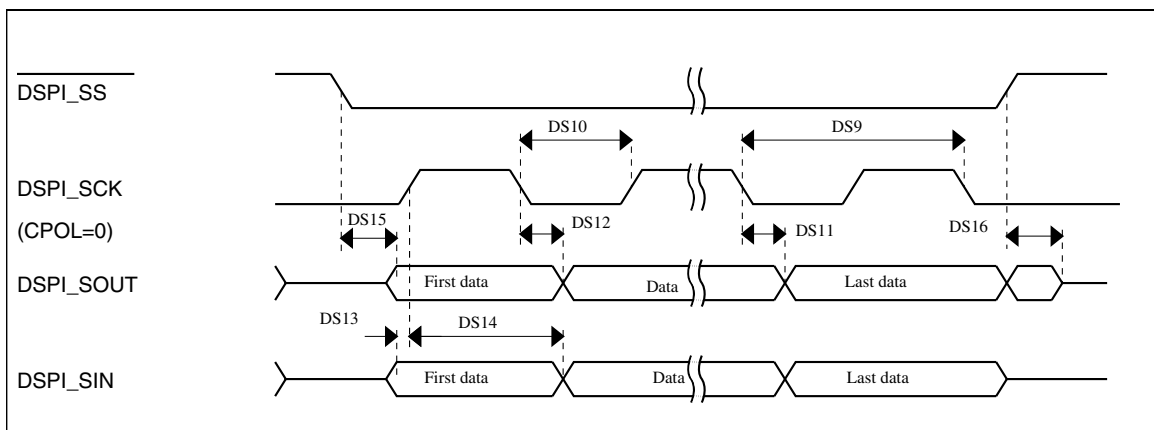


Figure 20. DSPI classic SPI timing — slave mode

6.8.6 DSPI switching specifications (full voltage range)

The DMA Serial Peripheral Interface (DSPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The tables below provides DSPI timing characteristics for classic SPI timing modes. Refer to the DSPI chapter of the Reference Manual for information on the modified transfer formats used for communicating with slower peripheral devices.

Table 42. Master mode DSPI timing (full voltage range)

| Num | Description | Min. | Max. | Unit | Notes |
|-----|--|---------------------------------|--------------------------|------|-------|
| | Operating voltage | 1.71 | 3.6 | V | 1 |
| | Frequency of operation | — | 12.5 | MHz | |
| DS1 | DSPI_SCK output cycle time | $4 \times t_{\text{BUS}}$ | — | ns | |
| DS2 | DSPI_SCK output high/low time | $(t_{\text{SCK}/2}) - 4$ | $(t_{\text{SCK}/2}) + 4$ | ns | |
| DS3 | DSPI_PCS n valid to DSPI_SCK delay | $(t_{\text{BUS}} \times 2) - 4$ | — | ns | 2 |
| DS4 | DSPI_SCK to DSPI_PCS n invalid delay | $(t_{\text{BUS}} \times 2) - 4$ | — | ns | 3 |
| DS5 | DSPI_SCK to DSPI_SOUT valid | — | 10 | ns | |
| DS6 | DSPI_SCK to DSPI_SOUT invalid | -4.5 | — | ns | |
| DS7 | DSPI_SIN to DSPI_SCK input setup | 20.5 | — | ns | |
| DS8 | DSPI_SCK to DSPI_SIN input hold | 0 | — | ns | |

1. The DSPI module can operate across the entire operating voltage for the processor, but to run across the full voltage range the maximum frequency of operation is reduced.
2. The delay is programmable in SPI x _CTAR n [PSSCK] and SPI x _CTAR n [CSSCK].
3. The delay is programmable in SPI x _CTAR n [PASC] and SPI x _CTAR n [ASC].

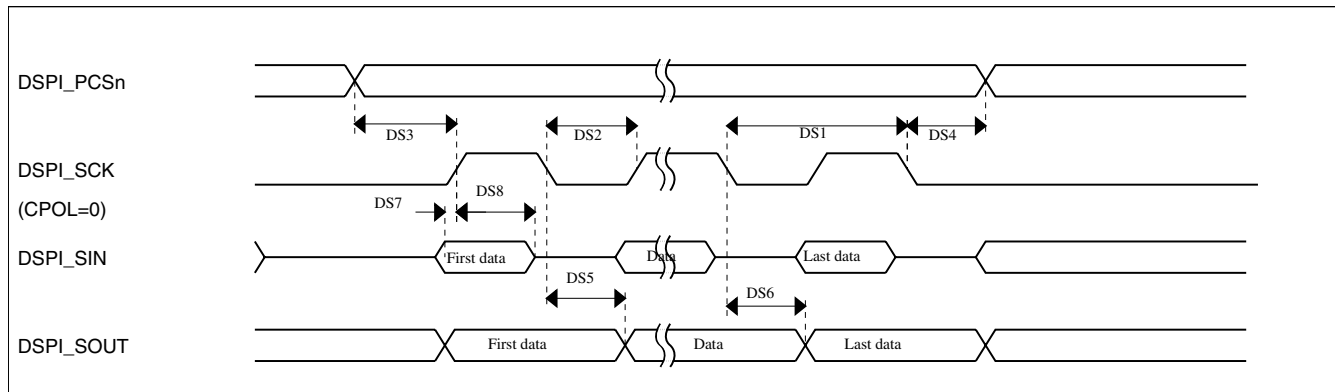
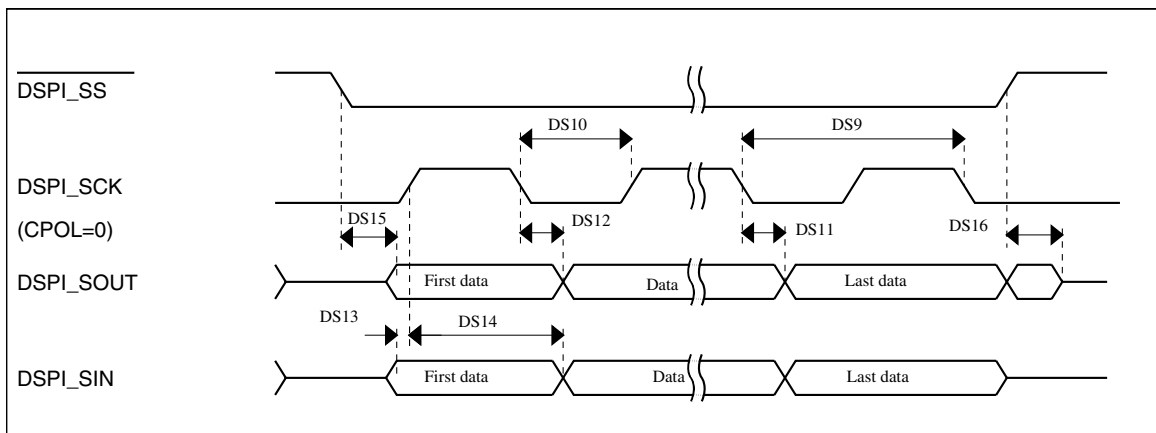


Figure 21. DSPI classic SPI timing — master mode

Table 43. Slave mode DSPI timing (full voltage range)

| Num | Description | Min. | Max. | Unit |
|------|--|--------------------|-------------------|------|
| | Operating voltage | 1.71 | 3.6 | V |
| | Frequency of operation | — | 6.25 | MHz |
| DS9 | DSPI_SCK input cycle time | $8 \times t_{BUS}$ | — | ns |
| DS10 | DSPI_SCK input high/low time | $(t_{SCK/2}) - 4$ | $(t_{SCK/2}) + 4$ | ns |
| DS11 | DSPI_SCK to DSPI_SOUT valid | — | 20 | ns |
| DS12 | DSPI_SCK to DSPI_SOUT invalid | 0 | — | ns |
| DS13 | DSPI_SIN to DSPI_SCK input setup | 2 | — | ns |
| DS14 | DSPI_SCK to DSPI_SIN input hold | 7 | — | ns |
| DS15 | $\overline{DSPI_SS}$ active to DSPI_SOUT driven | — | 19 | ns |
| DS16 | $\overline{DSPI_SS}$ inactive to DSPI_SOUT not driven | — | 19 | ns |

**Figure 22. DSPI classic SPI timing — slave mode**

6.8.7 I²C switching specifications

See [General switching specifications](#).

6.8.8 UART switching specifications

See [General switching specifications](#).

6.8.9 SDHC specifications

The following timing specs are defined at the chip I/O pin and must be translated appropriately to arrive at timing specs/constraints for the physical interface.

Table 44. SDHC switching specifications

| Num | Symbol | Description | Min. | Max. | Unit |
|---|------------------|---------------------------------------|------|------|------|
| | | Operating voltage | 2.7 | 3.6 | V |
| Card input clock | | | | | |
| SD1 | f _{pp} | Clock frequency (low speed) | 0 | 400 | kHz |
| | f _{pp} | Clock frequency (SD\SDIO full speed) | 0 | 25 | MHz |
| | f _{pp} | Clock frequency (MMC full speed) | 0 | 20 | MHz |
| | f _{OD} | Clock frequency (identification mode) | 0 | 400 | kHz |
| SD2 | t _{WL} | Clock low time | 7 | — | ns |
| SD3 | t _{WH} | Clock high time | 7 | — | ns |
| SD4 | t _{TLH} | Clock rise time | — | 3 | ns |
| SD5 | t _{THL} | Clock fall time | — | 3 | ns |
| SDHC output / card inputs SDHC_CMD, SDHC_DAT (reference to SDHC_CLK) | | | | | |
| SD6 | t _{OD} | SDHC output delay (output valid) | -5 | 6.5 | ns |
| SDHC input / card inputs SDHC_CMD, SDHC_DAT (reference to SDHC_CLK) | | | | | |
| SD7 | t _{ISU} | SDHC input setup time | 5 | — | ns |
| SD8 | t _{IH} | SDHC input hold time | 0 | — | ns |

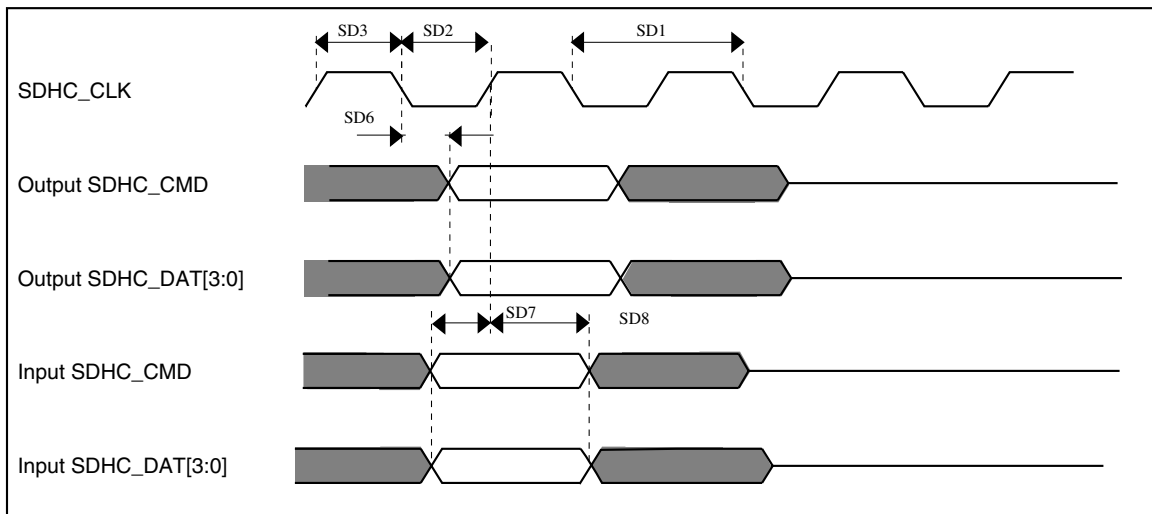


Figure 23. SDHC timing

6.8.10 I²S switching specifications

This section provides the AC timings for the I²S in master (clocks driven) and slave modes (clocks input). All timings are given for non-inverted serial clock polarity (TCR[TSCKP] = 0, RCR[RSCKP] = 0) and a non-inverted frame sync (TCR[TFSI] = 0, RCR[RFSI] = 0). If the polarity of the clock and/or the frame sync have been inverted, all the timings remain valid by inverting the clock signal (I2S_BCLK) and/or the frame sync (I2S_FS) shown in the figures below.

Table 45. I²S master mode timing

| Num | Description | Min. | Max. | Unit |
|-----|--|----------------------|------|-------------|
| | Operating voltage | 2.7 | 3.6 | V |
| S1 | I2S_MCLK cycle time | 2 x t _{SYS} | | ns |
| S2 | I2S_MCLK pulse width high/low | 45% | 55% | MCLK period |
| S3 | I2S_BCLK cycle time | 5 x t _{SYS} | — | ns |
| S4 | I2S_BCLK pulse width high/low | 45% | 55% | BCLK period |
| S5 | I2S_BCLK to I2S_FS output valid | — | 15 | ns |
| S6 | I2S_BCLK to I2S_FS output invalid | -2.5 | — | ns |
| S7 | I2S_BCLK to I2S_TXD valid | — | 15 | ns |
| S8 | I2S_BCLK to I2S_TXD invalid | -3 | — | ns |
| S9 | I2S_RXD/I2S_FS input setup before I2S_BCLK | 20 | — | ns |
| S10 | I2S_RXD/I2S_FS input hold after I2S_BCLK | 0 | — | ns |

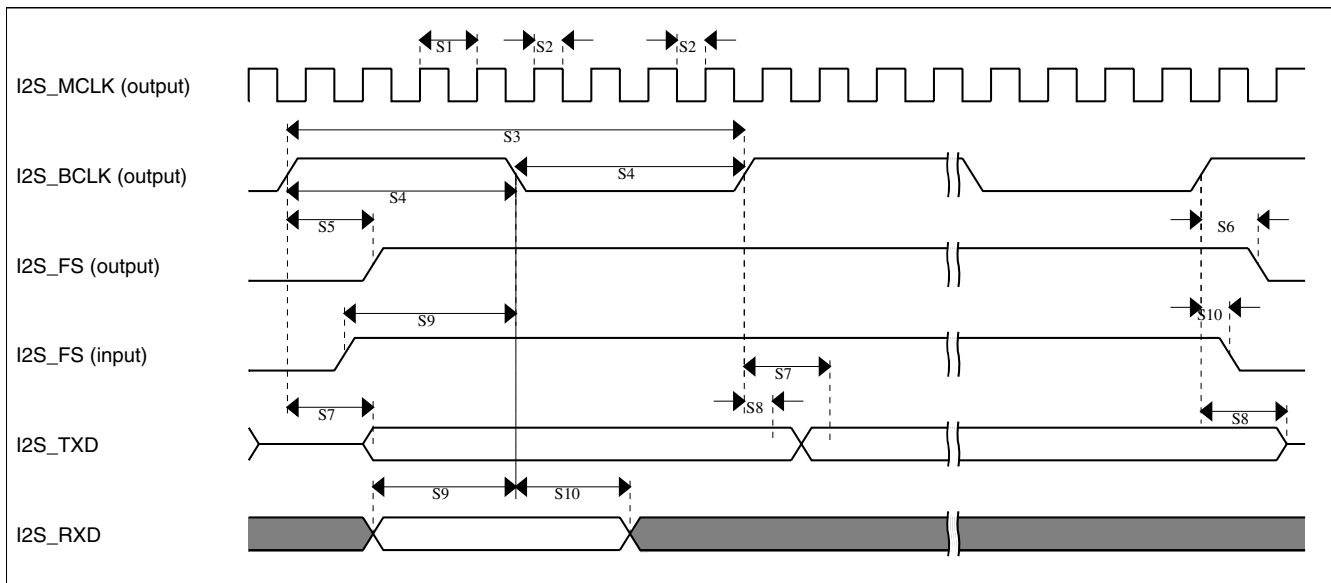
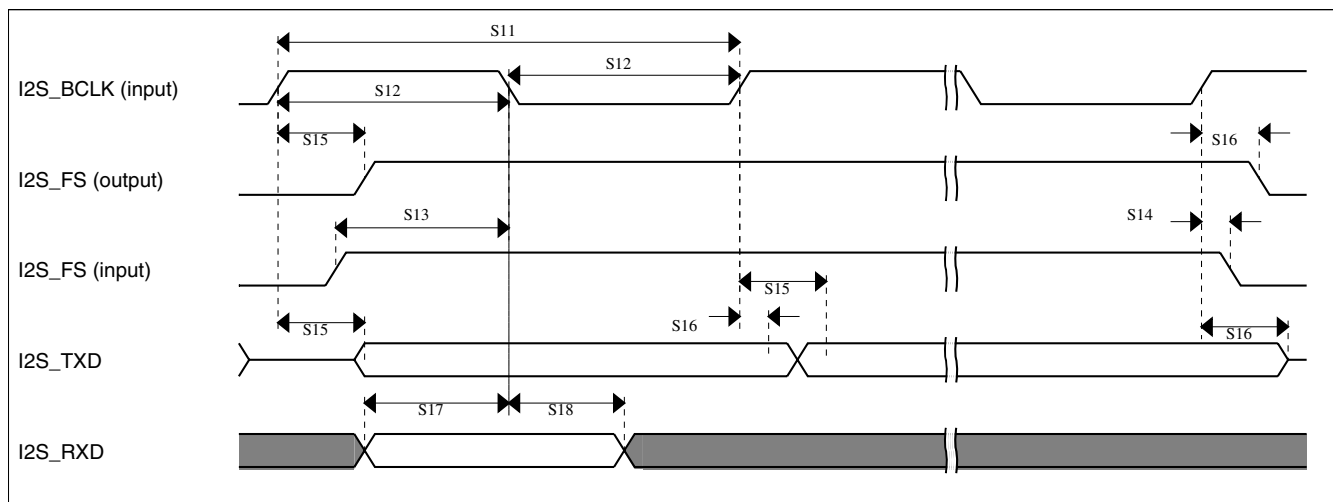


Figure 24. I²S timing — master mode

Table 46. I²S slave mode timing

| Num | Description | Min. | Max. | Unit |
|-----|---|----------------------|------|-------------|
| | Operating voltage | 2.7 | 3.6 | V |
| S11 | I2S_BCLK cycle time (input) | 8 x t _{sys} | — | ns |
| S12 | I2S_BCLK pulse width high/low (input) | 45% | 55% | MCLK period |
| S13 | I2S_FS input setup before I2S_BCLK | 10 | — | ns |
| S14 | I2S_FS input hold after I2S_BCLK | 3 | — | ns |
| S15 | I2S_BCLK to I2S_TXD/I2S_FS output valid | — | 20 | ns |
| S16 | I2S_BCLK to I2S_TXD/I2S_FS output invalid | 0 | — | ns |
| S17 | I2S_RXD setup before I2S_BCLK | 10 | — | ns |
| S18 | I2S_RXD hold after I2S_BCLK | 2 | — | ns |

**Figure 25. I²S timing — slave modes**

6.9 Human-machine interfaces (HMI)

6.9.1 TSI electrical specifications

Table 47. TSI electrical specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---------------------|------------------------------------|------|------|------|------|-------|
| V _{DDTSI} | Operating voltage | 1.71 | — | 3.6 | V | |
| C _{ELE} | Target electrode capacitance range | 1 | 20 | 500 | pF | 1 |
| f _{REFmax} | Reference oscillator frequency | — | 5.5 | 12.7 | MHz | 2 |
| f _{ELEmax} | Electrode oscillator frequency | — | 0.5 | 4.0 | MHz | 3 |

Table continues on the next page...

Table 47. TSI electrical specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|----------------------|---|--------|-------------|-----------|----------|-------|
| C _{REF} | Internal reference capacitor | 0.5 | 1 | 1.2 | pF | |
| V _{DELTA} | Oscillator delta voltage | 100 | 600 | 760 | mV | 4 |
| I _{REF} | Reference oscillator current source base current <ul style="list-style-type: none"> 1uA setting (REFCHRG=0) 32uA setting (REFCHRG=31) | — — | 1.133 36 | 1.5 50 | μA | 3, 5 |
| I _{ELE} | Electrode oscillator current source base current <ul style="list-style-type: none"> 1uA setting (EXTCHRG=0) 32uA setting (EXTCHRG=31) | — — | 1.133 36 | 1.5 50 | μA | 3,6 |
| Pres5 | Electrode capacitance measurement precision | — | 8.3333 | 38400 | % | 7 |
| Pres20 | Electrode capacitance measurement precision | — | 8.3333 | 38400 | % | 8 |
| Pres100 | Electrode capacitance measurement precision | — | 8.3333 | 38400 | % | 9 |
| MaxSens | Maximum sensitivity | 0.003 | 12.5 | — | fF/count | 10 |
| Res | Resolution | — | — | 16 | bits | |
| T _{Con20} | Response time @ 20 pF | 8 | 15 | 25 | μs | 11 |
| I _{TSI_RUN} | Current added in run mode | — | 55 | — | μA | |
| I _{TSI_LP} | Low power mode current adder | — | 1.3 | 2.5 | μA | 12 |

- The TSI module is functional with capacitance values outside this range. However, optimal performance is not guaranteed.
- CAPTRM=7, DELVOL=7, and fixed external capacitance of 20 pF.
- CAPTRM=0, DELVOL=2, and fixed external capacitance of 20 pF.
- CAPTRM=0, EXTCHRG=9, and fixed external capacitance of 20 pF.
- The programmable current source value is generated by multiplying the SCANC[REFCHRG] value and the base current.
- The programmable current source value is generated by multiplying the SCANC[EXTCHRG] value and the base current.
- Measured with a 5 pF electrode, reference oscillator frequency of 10 MHz, PS = 128, NSCN = 8; I_{ext} = 16.
- Measured with a 20 pF electrode, reference oscillator frequency of 10 MHz, PS = 128, NSCN = 2; I_{ext} = 16.
- Measured with a 20 pF electrode, reference oscillator frequency of 10 MHz, PS = 16, NSCN = 3; I_{ext} = 16.
- Sensitivity defines the minimum capacitance change when a single count from the TSI module changes, it is equal to $(C_{ref} * I_{ext}) / (I_{ref} * PS * NSCN)$. Sensitivity depends on the configuration used. The typical value listed is based on the following configuration: I_{ext} = 5 μA, EXTCHRG = 4, PS = 128, NSCN = 2, I_{ref} = 16 μA, REFCHRG = 15, C_{ref} = 1.0 pF. The minimum sensitivity describes the smallest possible capacitance that can be measured by a single count (this is the best sensitivity but is described as a minimum because it's the smallest number). The minimum sensitivity parameter is based on the following configuration: I_{ext} = 1 μA, EXTCHRG = 0, PS = 128, NSCN = 32, I_{ref} = 32 μA, REFCHRG = 31, C_{ref} = 0.5 pF
- Time to do one complete measurement of the electrode. Sensitivity resolution of 0.0133 pF, PS = 0, NSCN = 0, 1 electrode, DELVOL = 2, EXTCHRG = 15.
- CAPTRM=7, DELVOL=2, REFCHRG=0, EXTCHRG=4, PS=7, NSCN=0F, LPSCNITV=F, LPO is selected (1 kHz), and fixed external capacitance of 20 pF. Data is captured with an average of 7 periods window.

7 Dimensions

7.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to <http://www.freescale.com> and perform a keyword search for the drawing's document number:

| If you want the drawing for this package | Then use this document number |
|--|-------------------------------|
| 144-pin LQFP | 98ASS23177W |
| 144-pin MAPBGA | 98ASA00222D |

8 Pinout

8.1 K20 Signal Multiplexing and Pin Assignments

The following table shows the signals available on each pin and the locations of these pins on the devices supported by this document. The Port Control Module is responsible for selecting which ALT functionality is available on each pin.

| 144 LQFP | 144 MAPBGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|----------|------------|----------|-----------|-----------|------|-----------|-------------|------------|------|------------|------|--------|
| — | L5 | RESERVED | RESERVED | RESERVED | | | | | | | | |
| — | M5 | NC | NC | NC | | | | | | | | |
| — | A10 | NC | NC | NC | | | | | | | | |
| — | B10 | NC | NC | NC | | | | | | | | |
| — | C10 | NC | NC | NC | | | | | | | | |
| 1 | D3 | PTE0 | ADC1_SE4a | ADC1_SE4a | PTE0 | SPI1_PCS1 | UART1_TX | SDHC0_D1 | | I2C1_SDA | | |
| 2 | D2 | PTE1 | ADC1_SE5a | ADC1_SE5a | PTE1 | SPI1_SOUT | UART1_RX | SDHC0_D0 | | I2C1_SCL | | |
| 3 | D1 | PTE2 | ADC1_SE6a | ADC1_SE6a | PTE2 | SPI1_SCK | UART1_CTS_b | SDHC0_DCLK | | | | |
| 4 | E4 | PTE3 | ADC1_SE7a | ADC1_SE7a | PTE3 | SPI1_SIN | UART1_RTS_b | SDHC0_CMD | | | | |
| 5 | E5 | VDD | VDD | VDD | | | | | | | | |
| 6 | F6 | VSS | VSS | VSS | | | | | | | | |
| 7 | E3 | PTE4 | DISABLED | | PTE4 | SPI1_PCS0 | UART3_TX | SDHC0_D3 | | | | |
| 8 | E2 | PTE5 | DISABLED | | PTE5 | SPI1_PCS2 | UART3_RX | SDHC0_D2 | | | | |
| 9 | E1 | PTE6 | DISABLED | | PTE6 | SPI1_PCS3 | UART3_CTS_b | I2S0_MCLK | | I2S0_CLKIN | | |
| 10 | F4 | PTE7 | DISABLED | | PTE7 | | UART3_RTS_b | I2S0_RXD | | | | |

Pinout

| 144 LQFP | 144 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|----------|-------------|--------------------------------------|--------------------------------------|--------------------------------------|-------|------|-------------|--------------|------|------|------|--------|
| 11 | F3 | PTE8 | DISABLED | | PTE8 | | UART5_TX | I2S0_RX_FS | | | | |
| 12 | F2 | PTE9 | DISABLED | | PTE9 | | UART5_RX | I2S0_RX_BCLK | | | | |
| 13 | F1 | PTE10 | DISABLED | | PTE10 | | UART5_CTS_b | I2S0_TXD | | | | |
| 14 | G4 | PTE11 | DISABLED | | PTE11 | | UART5_RTS_b | I2S0_TX_FS | | | | |
| 15 | G3 | PTE12 | DISABLED | | PTE12 | | | I2S0_TX_BCLK | | | | |
| 16 | E6 | VDD | VDD | VDD | | | | | | | | |
| 17 | F7 | VSS | VSS | VSS | | | | | | | | |
| 18 | H3 | VSS | VSS | VSS | | | | | | | | |
| 19 | H1 | USB0_DP | USB0_DP | USB0_DP | | | | | | | | |
| 20 | H2 | USB0_DM | USB0_DM | USB0_DM | | | | | | | | |
| 21 | G1 | VOUT33 | VOUT33 | VOUT33 | | | | | | | | |
| 22 | G2 | VREGIN | VREGIN | VREGIN | | | | | | | | |
| 23 | J1 | ADC0_DP1 | ADC0_DP1 | ADC0_DP1 | | | | | | | | |
| 24 | J2 | ADC0_DM1 | ADC0_DM1 | ADC0_DM1 | | | | | | | | |
| 25 | K1 | ADC1_DP1 | ADC1_DP1 | ADC1_DP1 | | | | | | | | |
| 26 | K2 | ADC1_DM1 | ADC1_DM1 | ADC1_DM1 | | | | | | | | |
| 27 | L1 | PGA0_DP/ ADC0_DP0/ ADC1_DP3 | PGA0_DP/ ADC0_DP0/ ADC1_DP3 | PGA0_DP/ ADC0_DP0/ ADC1_DP3 | | | | | | | | |
| 28 | L2 | PGA0_DM/ ADC0_DM0/ ADC1_DM3 | PGA0_DM/ ADC0_DM0/ ADC1_DM3 | PGA0_DM/ ADC0_DM0/ ADC1_DM3 | | | | | | | | |
| 29 | M1 | PGA1_DP/ ADC1_DP0/ ADC0_DP3 | PGA1_DP/ ADC1_DP0/ ADC0_DP3 | PGA1_DP/ ADC1_DP0/ ADC0_DP3 | | | | | | | | |
| 30 | M2 | PGA1_DM/ ADC1_DM0/ ADC0_DM3 | PGA1_DM/ ADC1_DM0/ ADC0_DM3 | PGA1_DM/ ADC1_DM0/ ADC0_DM3 | | | | | | | | |
| 31 | H5 | VDDA | VDDA | VDDA | | | | | | | | |
| 32 | G5 | VREFH | VREFH | VREFH | | | | | | | | |
| 33 | G6 | VREFL | VREFL | VREFL | | | | | | | | |
| 34 | H6 | VSSA | VSSA | VSSA | | | | | | | | |
| 35 | K3 | ADC1_SE16/ CMP2_IN2/ ADC0_SE22 | ADC1_SE16/ CMP2_IN2/ ADC0_SE22 | ADC1_SE16/ CMP2_IN2/ ADC0_SE22 | | | | | | | | |
| 36 | J3 | ADC0_SE16/ CMP1_IN2/ ADC0_SE21 | ADC0_SE16/ CMP1_IN2/ ADC0_SE21 | ADC0_SE16/ CMP1_IN2/ ADC0_SE21 | | | | | | | | |

| 144 LQFP | 144 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|----------|-------------|--|--|--|-------|-------------|-------------|------|----------|--------------|------------------------|----------|
| | | ADC0_SE21 | | | | | | | | | | |
| 37 | M3 | VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18 | VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18 | VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18 | | | | | | | | |
| 38 | L3 | DAC0_OUT/ CMP1_IN3/ ADC0_SE23 | DAC0_OUT/ CMP1_IN3/ ADC0_SE23 | DAC0_OUT/ CMP1_IN3/ ADC0_SE23 | | | | | | | | |
| 39 | L4 | DAC1_OUT/ CMP2_IN3/ ADC1_SE23 | DAC1_OUT/ CMP2_IN3/ ADC1_SE23 | DAC1_OUT/ CMP2_IN3/ ADC1_SE23 | | | | | | | | |
| 40 | M7 | XTAL32 | XTAL32 | XTAL32 | | | | | | | | |
| 41 | M6 | EXTAL32 | EXTAL32 | EXTAL32 | | | | | | | | |
| 42 | L6 | VBAT | VBAT | VBAT | | | | | | | | |
| 43 | — | VDD | VDD | VDD | | | | | | | | |
| 44 | — | VSS | VSS | VSS | | | | | | | | |
| 45 | M4 | PTE24 | ADC0_SE17 | ADC0_SE17 | PTE24 | CAN1_TX | UART4_TX | | | EWM_OUT_b | | |
| 46 | K5 | PTE25 | ADC0_SE18 | ADC0_SE18 | PTE25 | CAN1_RX | UART4_RX | | | EWM_IN | | |
| 47 | K4 | PTE26 | DISABLED | | PTE26 | | UART4_CTS_b | | | RTC_CLKOUT | USB_CLKIN | |
| 48 | J4 | PTE27 | DISABLED | | PTE27 | | UART4_RTS_b | | | | | |
| 49 | H4 | PTE28 | DISABLED | | PTE28 | | | | | | | |
| 50 | J5 | PTA0 | JTAG_TCLK/ SWD_CLK/ EZP_CLK | TSIO_CH1 | PTA0 | UART0_CTS_b | FTM0_CH5 | | | | JTAG_TCLK/ SWD_CLK | EZP_CLK |
| 51 | J6 | PTA1 | JTAG_TDI/ EZP_DI | TSIO_CH2 | PTA1 | UART0_RX | FTM0_CH6 | | | | JTAG_TDI | EZP_DI |
| 52 | K6 | PTA2 | JTAG_TDO/ TRACE_SWO/ EZP_DO | TSIO_CH3 | PTA2 | UART0_TX | FTM0_CH7 | | | | JTAG_TDO/ TRACE_SWO | EZP_DO |
| 53 | K7 | PTA3 | JTAG_TMS/ SWD_DIO | TSIO_CH4 | PTA3 | UART0_RTS_b | FTM0_CH0 | | | | JTAG_TMS/ SWD_DIO | |
| 54 | L7 | PTA4 | NMI_b/ EZP_CS_b | TSIO_CH5 | PTA4 | | FTM0_CH1 | | | | NMI_b | EZP_CS_b |
| 55 | M8 | PTA5 | DISABLED | | PTA5 | | FTM0_CH2 | | CMP2_OUT | I2S0_RX_BCLK | JTAG_TRST | |
| 56 | E7 | VDD | VDD | VDD | | | | | | | | |
| 57 | G7 | VSS | VSS | VSS | | | | | | | | |
| 58 | J7 | PTA6 | DISABLED | | PTA6 | | FTM0_CH3 | | | | TRACE_CLKOUT | |

Pinout

| 144 LQFP | 144 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|----------|-------------|----------|--------------------------------------|--------------------------------------|-------|-----------|-------------|------------|------|-------------|-------------|--------|
| 59 | J8 | PTA7 | ADC0_SE10 | ADC0_SE10 | PTA7 | | FTM0_CH4 | | | | TRACE_D3 | |
| 60 | K8 | PTA8 | ADC0_SE11 | ADC0_SE11 | PTA8 | | FTM1_CH0 | | | FTM1_QD_PHA | TRACE_D2 | |
| 61 | L8 | PTA9 | DISABLED | | PTA9 | | FTM1_CH1 | | | FTM1_QD_PHB | TRACE_D1 | |
| 62 | M9 | PTA10 | DISABLED | | PTA10 | | FTM2_CH0 | | | FTM2_QD_PHA | TRACE_D0 | |
| 63 | L9 | PTA11 | DISABLED | | PTA11 | | FTM2_CH1 | | | FTM2_QD_PHB | | |
| 64 | K9 | PTA12 | CMP2_IN0 | CMP2_IN0 | PTA12 | CAN0_TX | FTM1_CH0 | | | I2S0_TXD | FTM1_QD_PHA | |
| 65 | J9 | PTA13 | CMP2_IN1 | CMP2_IN1 | PTA13 | CAN0_RX | FTM1_CH1 | | | I2S0_TX_FS | FTM1_QD_PHB | |
| 66 | L10 | PTA14 | DISABLED | | PTA14 | SPI0_PCS0 | UART0_TX | | | I2S0_TX_CLK | | |
| 67 | L11 | PTA15 | DISABLED | | PTA15 | SPI0_SCK | UART0_RX | | | I2S0_RXD | | |
| 68 | K10 | PTA16 | DISABLED | | PTA16 | SPI0_SOUT | UART0_CS_b | | | I2S0_RX_FS | | |
| 69 | K11 | PTA17 | ADC1_SE17 | ADC1_SE17 | PTA17 | SPI0_SIN | UART0_RTS_b | | | I2S0_MCLK | I2S0_CLKIN | |
| 70 | E8 | VDD | VDD | VDD | | | | | | | | |
| 71 | G8 | VSS | VSS | VSS | | | | | | | | |
| 72 | M12 | PTA18 | EXTAL | EXTAL | PTA18 | | FTM0_FLT2 | FTM_CLKIN0 | | | | |
| 73 | M11 | PTA19 | XTAL | XTAL | PTA19 | | FTM1_FLT0 | FTM_CLKIN1 | | LPT0_ALT1 | | |
| 74 | L12 | RESET_b | RESET_b | RESET_b | | | | | | | | |
| 75 | K12 | PTA24 | DISABLED | | PTA24 | | | | | FB_A29 | | |
| 76 | J12 | PTA25 | DISABLED | | PTA25 | | | | | FB_A28 | | |
| 77 | J11 | PTA26 | DISABLED | | PTA26 | | | | | FB_A27 | | |
| 78 | J10 | PTA27 | DISABLED | | PTA27 | | | | | FB_A26 | | |
| 79 | H12 | PTA28 | DISABLED | | PTA28 | | | | | FB_A25 | | |
| 80 | H11 | PTA29 | DISABLED | | PTA29 | | | | | FB_A24 | | |
| 81 | H10 | PTB0 | / ADC0_SE8/ ADC1_SE8/ TSI0_CH0 | / ADC0_SE8/ ADC1_SE8/ TSI0_CH0 | PTB0 | I2C0_SCL | FTM1_CH0 | | | FTM1_QD_PHA | | |
| 82 | H9 | PTB1 | / ADC0_SE9/ ADC1_SE9/ TSI0_CH6 | / ADC0_SE9/ ADC1_SE9/ TSI0_CH6 | PTB1 | I2C0_SDA | FTM1_CH1 | | | FTM1_QD_PHB | | |
| 83 | G12 | PTB2 | / ADC0_SE12/ TSI0_CH7 | / ADC0_SE12/ TSI0_CH7 | PTB2 | I2C0_SCL | UART0_RTS_b | | | FTM0_FLT3 | | |

| 144 LQFP | 144 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|----------|-------------|----------|-----------------------|-----------------------|-------|-----------|-------------|--------------|---------|-------------|------|--------|
| 84 | G11 | PTB3 | / ADC0_SE13/TSIO_CH8 | / ADC0_SE13/TSIO_CH8 | PTB3 | I2C0_SDA | UART0_CTS_b | | | FTM0_FLT0 | | |
| 85 | G10 | PTB4 | / ADC1_SE10 | / ADC1_SE10 | PTB4 | | | | | FTM1_FLT0 | | |
| 86 | G9 | PTB5 | / ADC1_SE11 | / ADC1_SE11 | PTB5 | | | | | FTM2_FLT0 | | |
| 87 | F12 | PTB6 | / ADC1_SE12 | / ADC1_SE12 | PTB6 | | | | FB_AD23 | | | |
| 88 | F11 | PTB7 | / ADC1_SE13 | / ADC1_SE13 | PTB7 | | | | FB_AD22 | | | |
| 89 | F10 | PTB8 | | | PTB8 | | UART3_RTS_b | | FB_AD21 | | | |
| 90 | F9 | PTB9 | | | PTB9 | SPI1_PCS1 | UART3_CTS_b | | FB_AD20 | | | |
| 91 | E12 | PTB10 | / ADC1_SE14 | / ADC1_SE14 | PTB10 | SPI1_PCS0 | UART3_RX | | FB_AD19 | FTM0_FLT1 | | |
| 92 | E11 | PTB11 | / ADC1_SE15 | / ADC1_SE15 | PTB11 | SPI1_SCK | UART3_TX | | FB_AD18 | FTM0_FLT2 | | |
| 93 | H7 | VSS | VSS | VSS | | | | | | | | |
| 94 | F5 | VDD | VDD | VDD | | | | | | | | |
| 95 | E10 | PTB16 | /TSIO_CH9 | /TSIO_CH9 | PTB16 | SPI1_SOUT | UART0_RX | | FB_AD17 | EWM_IN | | |
| 96 | E9 | PTB17 | /TSIO_CH10 | /TSIO_CH10 | PTB17 | SPI1_SIN | UART0_TX | | FB_AD16 | EWM_OUT_b | | |
| 97 | D12 | PTB18 | /TSIO_CH11 | /TSIO_CH11 | PTB18 | CAN0_TX | FTM2_CH0 | I2S0_TX_BCLK | FB_AD15 | FTM2_QD_PHA | | |
| 98 | D11 | PTB19 | /TSIO_CH12 | /TSIO_CH12 | PTB19 | CAN0_RX | FTM2_CH1 | I2S0_TX_FS | FB_OE_b | FTM2_QD_PHB | | |
| 99 | D10 | PTB20 | | | PTB20 | SPI2_PCS0 | | | FB_AD31 | CMP0_OUT | | |
| 100 | D9 | PTB21 | | | PTB21 | SPI2_SCK | | | FB_AD30 | CMP1_OUT | | |
| 101 | C12 | PTB22 | | | PTB22 | SPI2_SOUT | | | FB_AD29 | CMP2_OUT | | |
| 102 | C11 | PTB23 | | | PTB23 | SPI2_SIN | SPI0_PCS5 | | FB_AD28 | | | |
| 103 | B12 | PTC0 | / ADC0_SE14/TSIO_CH13 | / ADC0_SE14/TSIO_CH13 | PTC0 | SPI0_PCS4 | PDB0_EXT RG | I2S0_TXD | FB_AD14 | | | |
| 104 | B11 | PTC1 | / ADC0_SE15/TSIO_CH14 | / ADC0_SE15/TSIO_CH14 | PTC1 | SPI0_PCS3 | UART1_RTS_b | FTM0_CH0 | FB_AD13 | | | |
| 105 | A12 | PTC2 | / ADC0_SE4 | / ADC0_SE4 | PTC2 | SPI0_PCS2 | UART1_CTS_b | FTM0_CH1 | FB_AD12 | | | |

Pinout

| 144 LQFP | 144 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|----------|-------------|----------|---------------------------------|---------------------------------|-------|-----------|-----------------|------------------|--|-----------|------|--------|
| | | | b/ CMP1_IN0/ TSIO_CH15 | b/ CMP1_IN0/ TSIO_CH15 | | | | | | | | |
| 106 | A11 | PTC3 | /CMP1_IN1 | /CMP1_IN1 | PTC3 | SPI0_PCS1 | UART1_RX | FTM0_CH2 | FB_CLKOUT | | | |
| 107 | H8 | VSS | VSS | VSS | | | | | | | | |
| 108 | — | VDD | VDD | VDD | | | | | | | | |
| 109 | A9 | PTC4 | | | PTC4 | SPI0_PCS0 | UART1_TX | FTM0_CH3 | FB_AD11 | CMP1_OUT | | |
| 110 | D8 | PTC5 | | | PTC5 | SPI0_SCK | | LPT0_ALT2 | FB_AD10 | CMP0_OUT | | |
| 111 | C8 | PTC6 | /CMP0_IN0 | /CMP0_IN0 | PTC6 | SPI0_SOUT | PDB0_EXT RG | | FB_AD9 | | | |
| 112 | B8 | PTC7 | /CMP0_IN1 | /CMP0_IN1 | PTC7 | SPI0_SIN | | | FB_AD8 | | | |
| 113 | A8 | PTC8 | / ADC1_SE4 b/ CMP0_IN2 | / ADC1_SE4 b/ CMP0_IN2 | PTC8 | | I2S0_MCLK | I2S0_CLKIN | FB_AD7 | | | |
| 114 | D7 | PTC9 | / ADC1_SE5 b/ CMP0_IN3 | / ADC1_SE5 b/ CMP0_IN3 | PTC9 | | | I2S0_RX_B CLK | FB_AD6 | FTM2_FLT0 | | |
| 115 | C7 | PTC10 | / ADC1_SE6 b/ CMP0_IN4 | / ADC1_SE6 b/ CMP0_IN4 | PTC10 | I2C1_SCL | | I2S0_RX_F S | FB_AD5 | | | |
| 116 | B7 | PTC11 | / ADC1_SE7 b | / ADC1_SE7 b | PTC11 | I2C1_SDA | | I2S0_RXD | FB_RW_b | | | |
| 117 | A7 | PTC12 | | | PTC12 | | UART4_RT S_b | | FB_AD27 | | | |
| 118 | D6 | PTC13 | | | PTC13 | | UART4_CT S_b | | FB_AD26 | | | |
| 119 | C6 | PTC14 | | | PTC14 | | UART4_RX | | FB_AD25 | | | |
| 120 | B6 | PTC15 | | | PTC15 | | UART4_TX | | FB_AD24 | | | |
| 121 | — | VSS | VSS | VSS | | | | | | | | |
| 122 | — | VDD | VDD | VDD | | | | | | | | |
| 123 | A6 | PTC16 | | | PTC16 | CAN1_RX | UART3_RX | | FB_CS5_b/ FB_TSIZ1/ FB_BE23_1 6_BLS15_8 _b | | | |
| 124 | D5 | PTC17 | | | PTC17 | CAN1_TX | UART3_TX | | FB_CS4_b/ FB_TSIZ0/ FB_BE31_2 4_BLS7_0 _b | | | |
| 125 | C5 | PTC18 | | | PTC18 | | UART3_RT S_b | | FB_TBST_b /FB_CS2_b/ FB_BE15_8 | | | |

| 144 LQFP | 144 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|----------|-------------|----------|--------------|--------------|-------|-----------|-------------|-------------|----------------------------------|-----------|------|--------|
| | | | | | | | | | _BLS23_16_b | | | |
| 126 | B5 | PTC19 | | | PTC19 | | UART3_CTS_b | | FB_CS3_b/ FB_BE7_0_BLS31_24_b | FB_TA_b | | |
| 127 | A5 | PTD0 | | | PTD0 | SPI0_PCS0 | UART2_RTS_b | | FB_ALE/ FB_CS1_b/ FB_TS_b | | | |
| 128 | D4 | PTD1 | / ADC0_SE5_b | / ADC0_SE5_b | PTD1 | SPI0_SCK | UART2_CTS_b | | FB_CS0_b | | | |
| 129 | C4 | PTD2 | | | PTD2 | SPI0_SOUT | UART2_RX | | FB_AD4 | | | |
| 130 | B4 | PTD3 | | | PTD3 | SPI0_SIN | UART2_TX | | FB_AD3 | | | |
| 131 | A4 | PTD4 | | | PTD4 | SPI0_PCS1 | UART0_RTS_b | FTM0_CH4 | FB_AD2 | EWM_IN | | |
| 132 | A3 | PTD5 | / ADC0_SE6_b | / ADC0_SE6_b | PTD5 | SPI0_PCS2 | UART0_CTS_b | FTM0_CH5 | FB_AD1 | EWM_OUT_b | | |
| 133 | A2 | PTD6 | / ADC0_SE7_b | / ADC0_SE7_b | PTD6 | SPI0_PCS3 | UART0_RX | FTM0_CH6 | FB_AD0 | FTM0_FLT0 | | |
| 134 | M10 | VSS | VSS | VSS | | | | | | | | |
| 135 | F8 | VDD | VDD | VDD | | | | | | | | |
| 136 | A1 | PTD7 | | | PTD7 | CMT_IRO | UART0_TX | FTM0_CH7 | | FTM0_FLT1 | | |
| 137 | C9 | PTD8 | DISABLED | | PTD8 | I2C0_SCL | UART5_RX | | | FB_A16 | | |
| 138 | B9 | PTD9 | DISABLED | | PTD9 | I2C0_SDA | UART5_TX | | | FB_A17 | | |
| 139 | B3 | PTD10 | DISABLED | | PTD10 | | UART5_RTS_b | | | FB_A18 | | |
| 140 | B2 | PTD11 | DISABLED | | PTD11 | SPI2_PCS0 | UART5_CTS_b | SDHC0_CLKIN | | FB_A19 | | |
| 141 | B1 | PTD12 | DISABLED | | PTD12 | SPI2_SCK | | SDHC0_D4 | | FB_A20 | | |
| 142 | C3 | PTD13 | DISABLED | | PTD13 | SPI2_SOUT | | SDHC0_D5 | | FB_A21 | | |
| 143 | C2 | PTD14 | DISABLED | | PTD14 | SPI2_SIN | | SDHC0_D6 | | FB_A22 | | |
| 144 | C1 | PTD15 | DISABLED | | PTD15 | SPI2_PCS1 | | SDHC0_D7 | | FB_A23 | | |

8.2 K20 Pinouts

The below figure shows the pinout diagram for the devices supported by this document. Many signals may be multiplexed onto a single pin. To determine what signals can be used on which pin, see the previous section.

Pinout

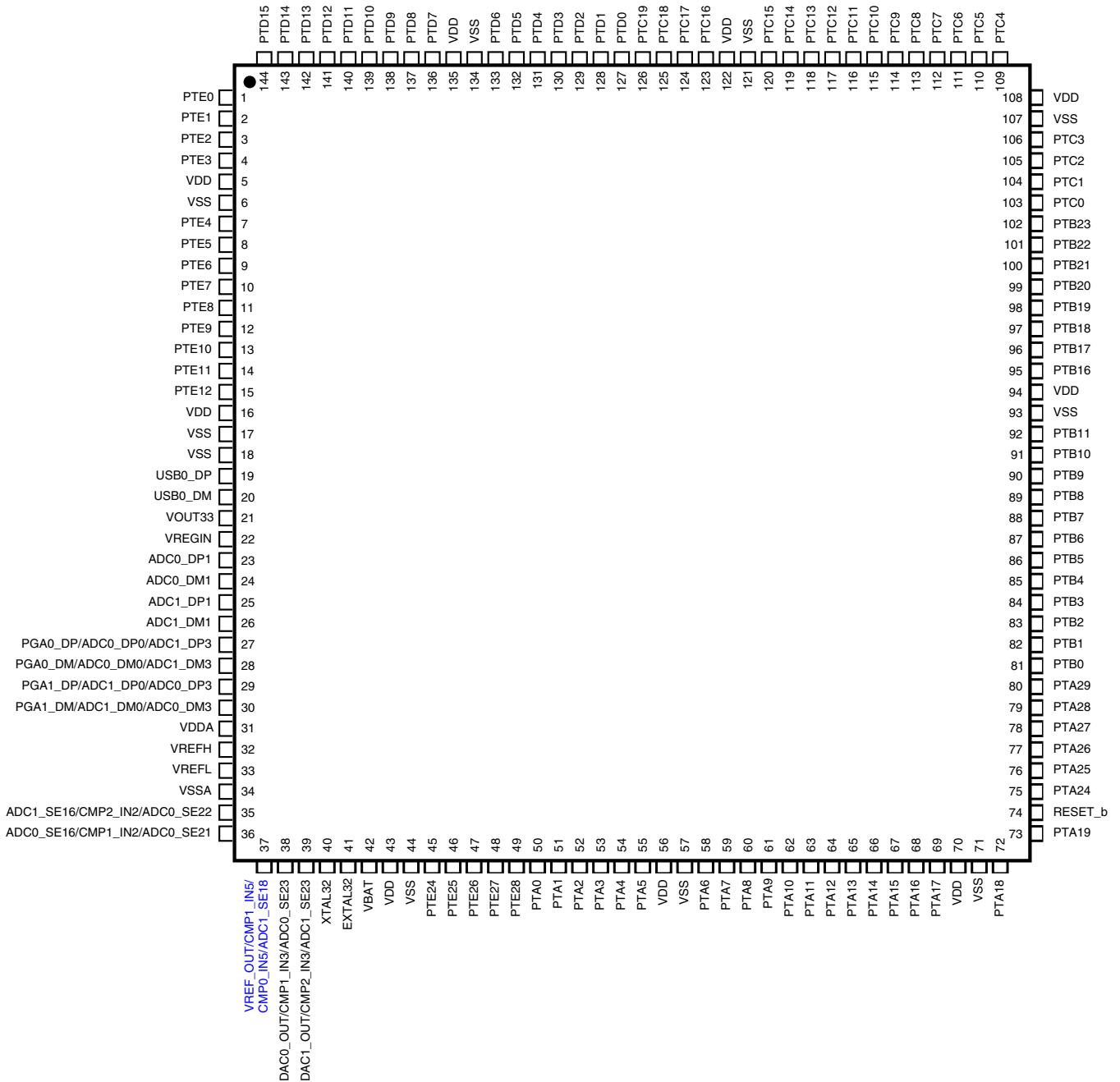


Figure 26. K20 144 LQFP Pinout Diagram

| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | |
|---|-----------------------------------|-----------------------------------|--|-------------------------------------|----------|---------|--------|------|-------|-------|-------|---------|---|
| A | PTD7 | PTD6 | PTD5 | PTD4 | PTD0 | PTC16 | PTC12 | PTC8 | PTC4 | NC | PTC3 | PTC2 | A |
| B | PTD12 | PTD11 | PTD10 | PTD3 | PTC19 | PTC15 | PTC11 | PTC7 | PTD9 | NC | PTC1 | PTC0 | B |
| C | PTD15 | PTD14 | PTD13 | PTD2 | PTC18 | PTC14 | PTC10 | PTC6 | PTD8 | NC | PTB23 | PTB22 | C |
| D | PTE2 | PTE1 | PTE0 | PTD1 | PTC17 | PTC13 | PTC9 | PTC5 | PTB21 | PTB20 | PTB19 | PTB18 | D |
| E | PTE6 | PTE5 | PTE4 | PTE3 | VDD | VDD | VDD | VDD | PTB17 | PTB16 | PTB11 | PTB10 | E |
| F | PTE10 | PTE9 | PTE8 | PTE7 | VDD | VSS | VSS | VDD | PTB9 | PTB8 | PTB7 | PTB6 | F |
| G | VOOUT33 | VREGIN | PTE12 | PTE11 | VREFH | VREFL | VSS | VSS | PTB5 | PTB4 | PTB3 | PTB2 | G |
| H | USB0_DP | USB0_DM | VSS | PTE28 | VDDA | VSSA | VSS | VSS | PTB1 | PTB0 | PTA29 | PTA28 | H |
| J | ADC0_DP1 | ADC0_DM1 | ADC0_SE16/ CMP1_IN2/ ADC0_SE21 | PTE27 | PTA0 | PTA1 | PTA6 | PTA7 | PTA13 | PTA27 | PTA26 | PTA25 | J |
| K | ADC1_DP1 | ADC1_DM1 | ADC1_SE16/ CMP2_IN2/ ADC0_SE22 | PTE26 | PTE25 | PTA2 | PTA3 | PTA8 | PTA12 | PTA16 | PTA17 | PTA24 | K |
| L | PGA0_DP/ ADC0_DP0/ ADC1_DP3 | PGA0_DM/ ADC0_DM0/ ADC1_DM3 | DAC0_OUT/ CMP1_IN3/ ADC0_SE23 | DAC1_OUT/ CMP2_IN3/ ADC1_SE23 | RESERVED | VBAT | PTA4 | PTA9 | PTA11 | PTA14 | PTA15 | RESET_b | L |
| M | PGA1_DP/ ADC1_DP0/ ADC0_DP3 | PGA1_DM/ ADC1_DM0/ ADC0_DM3 | VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18 | PTE24 | NC | EXTAL32 | XTAL32 | PTA5 | PTA10 | VSS | PTA19 | PTA18 | M |
| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | |

Figure 27. K20 144 MAPBGA Pinout Diagram

9 Revision History

The following table provides a revision history for this document.

Table 48. Revision History

| Rev. No. | Date | Substantial Changes |
|----------|---------|-------------------------|
| 1 | 11/2010 | Initial public revision |

Table continues on the next page...

Table 48. Revision History (continued)

| Rev. No. | Date | Substantial Changes |
|----------|--------|--|
| 2 | 3/2011 | Many updates throughout |
| 3 | 3/2011 | Added sections that were inadvertently removed in previous revision |
| 4 | 3/2011 | Reworded I_{IC} footnote in "Voltage and Current Operating Requirements" table. Added paragraph to "Peripheral operating requirements and behaviors" section. Added "JTAG full voltage range electricals" table to the "JTAG electricals" section. |
| 5 | 6/2011 | <ul style="list-style-type: none"> • Changed supported part numbers per new part number scheme • Changed <i>DC injection current</i> specs in "Voltage and current operating requirements" table • Changed <i>Input leakage current</i> and <i>internal pullup/pulldown resistor</i> specs in "Voltage and current operating behaviors" table • Split <i>Low power stop mode current</i> specs by temperature range in "Power consumption operating behaviors" table • Changed typical I_{DD_VBAT} spec in "Power consumption operating behaviors" table • Added LPTMR clock specs to "Device clock specifications" table • Changed <i>Minimum external reset pulse width</i> in "General switching specifications" table • Changed <i>PLL operating current</i> in "MCG specifications" table • Added footnote to <i>PLL period jitter</i> in "MCG specifications" table • Changed <i>Supply current</i> in "Oscillator DC electrical specifications" table • Changed <i>Crystal startup time</i> in "Oscillator frequency specifications" table • Changed <i>Operating voltage</i> in "EzPort switching specifications" table • Changed title of "FlexBus switching specifications" table and added Output valid and hold specs • Added "FlexBus full range switching specifications" table • Changed <i>ADC asynchronous clock source</i> specs in "16-bit ADC characteristics" table • Changed <i>Gain</i> spec in "16-bit ADC with PGA characteristics" table • Added typical <i>Input DC current</i> to "16-bit ADC with PGA characteristics" table • Changed <i>Input offset voltage</i> and <i>ENOB</i> notes field in "16-bit ADC with PGA characteristics" table • Changed <i>Analog comparator initialization delay</i> in "Comparator and 6-bit DAC electrical specifications" • Changed <i>Code-to-code settling time</i>, <i>DAC output voltage range low</i>, and <i>Temperature coefficient offset voltage</i> in "12-bit DAC operating behaviors" table • Changed <i>Temperature drift</i> and <i>Load regulation</i> in "VREF full-range operating behaviors" table • Changed <i>Regulator output voltage</i> in "USB VREG electrical specifications" table • Changed I_{LIM} description and specs in "USB VREG electrical specifications" table • Changed <i>DSPI_SCK cycle time</i> specs in "DSPI timing" tables • Changed <i>DSPI_SS</i> specs in "Slave mode DSPI timing (low-speed mode)" table • Changed <i>DSPI_SCK to DSPI_SOUT valid</i> spec in "Slave mode DSPI timing (high-speed mode)" table • Changed <i>Reference oscillator current source base current</i> spec and added <i>Low-power current adder</i> footer in "TSI electrical specifications" table |

Table continues on the next page...

Table 48. Revision History (continued)

| Rev. No. | Date | Substantial Changes |
|----------|--------|---|
| 6 | 9/2011 | <ul style="list-style-type: none"> • Added AC electrical specifications. • Replaced TBDs with silicon data throughout. • In "Power mode transition operating behaviors" table, removed entry times. • Updated "EMC radiated emissions operating behaviors" to remove SAE level and also added data for 144LQFP. • Clarified "EP7" in "EzPort switching specifications" table and "EzPort Timing Diagram". • Added "ENOB vs. ADC_CLK for 16-bit differential and 16-bit single-ended modes" figures. • Updated I_{DD_RUN} numbers in 'Power consumption operating behaviors' section. • Clarified 'Diagram: Typical IDD_RUN operating behavior' section and updated 'Run mode supply current vs. core frequency — all peripheral clocks disabled' figure. • In 'Voltage reference electrical specifications' section, updated C_L, V_{tdrift}, and V_{vdrift} values. • In 'USB electrical specifications' section, updated V_{DP_SRC}, I_{DDstby}, and V_{Reg33out} values. |

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